

BCM53158XU

Ultra-Low Power Layer2 GE/FE Switch with 10G Uplinks

General Descriptions

Broadcom's BCM53158XU is a family of highly integrated Ethernet switches that are optimally designed for cost-effective low-power applications in the SMB, Enterprise, Service-Provider, and SOHO markets that rapidly transition to Gigabit-Ethernet connectivity and beyond.

The BCM53158XU is based on the industry-leading 28 nm RoboSwitch™ architecture, also known as Robo 2. The product line includes multiple models with 6 to 15 interfaces that support 100M/1GE/2.5GE and 10GE of bandwidth.

The BCM53158XU is designed for standalone low portcount configurations and high port-count configurations with support for cascading.

The BCM53158XU allows customers to design complete product platforms that target new cost-effective low-power applications demanding 1GE/10GbE connectivity. Among those, SMB switch with 10G uplinks, Enterprise switches, routers and security appliances, next generation Industrial Ethernet switches, and Service Provider access equipment.

The BCM53158XU is also designed to support basic applications that include Auto DOS, Auto VOIP, Auto QoS, and more. The product line takes advantage of a low-power integrated ARM Cortex-M7 CPU to offer on-chip support for certain protocols, including Auto IGMP snooping as well as tools for monitoring and troubleshooting. The product line is offered in Commercial-grade as well as Industrial-grade temperature ranges.

Features

- ARM Cortex-M7 at up to 400 MHz.
- Operational mode: Unmanaged.
- Up to 8×10/100/1000BASE-T ports with integrated ultra-low-power GPHYs.
- Up to 1×QSGMII with integrated SerDes.
- Up to 2×10G XFI with KR support.
- 1 × RGMII.

- Switch cascading.
- 16K entry MAC address table.
- 1K multicast group support.
- 128 KB packet buffer.
- srTCM and trTCM meters (support color aware and color blind modes).
- Eight CoS queues per port with priority flow-control.
- IEEE 802.1p, MAC, and DSCP packet classification.
- Auto Loop detection.
- Auto DoS.
- Auto VOIP.
- Auto QOS.
- Auto IGMP snooping.
- 1K packets and bytes counters.
- IEEE 802.3az Energy Efficient Ethernet (EEE).
- Jumbo frame support: up to 9728 bytes.
- 311-pin, 13×13 mm² FBGA package.
- JTAG support.
- Includes one UART and MDIO interface, seven I²C interfaces, and 9 GPIOs (via the MFIO).

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Figure 1: Functional Block Diagram

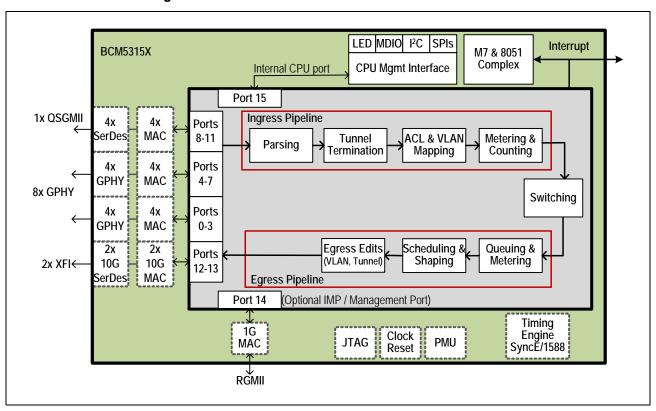


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Chapter 1: Introduction

1.1 Overview

This document provides details of the functional, operational, and electrical characteristics of the Broadcom[®] BCM53158XU. This document is for designers interested in integrating the BCM53158XU switches into their hardware designs and for others who need specific data about the physical characteristics and operation of the BCM53158XU switches.

The BCM53158XU is a family of highly integrated Ethernet switches that are optimally designed for cost-effective low-power applications in the SMB, Enterprise, Service-Provider, SOHO, and Industrial-Ethernet markets. The BCM53158XU is the first family of products in the RoboSwitch® product line to introduce 10 GE ports, which are relevant in markets that are rapidly transitioning to Gigabit-Ethernet connectivity anywhere.

The BCM53158XU switch core supports full-duplex packet forwarding bandwidth of 33 Gb/s for all packet lengths (64 byte to 9720 Jumbo frames).

The family is based on a core technology that supports:

- Eight 10/100/1000BASE-TX ports with integrated Gigabit MACs (GMACs), and integrated PHYs (GPHYs)
- One QSGMII port
- Two 10GE/2.5GE/1GE XFI ports with integrated XMACs
- One RGMII port for PHY-less connection to the management agent (available only in full-duplex mode)
- An integrated Motorola SPI-compatible interface
- High-performance, integrated packet buffer memory
- An address resolution engine

The GMACs support full-duplex and half-duplex modes for 10 Mb/s and 100 Mb/s, and full-duplex for 1000 Mb/s. Flow control is supported in half-duplex mode with backpressure. In full-duplex mode, IEEE 802.3x frame-based flow control is supported. The GMACs are IEEE 802.3-compliant and support a maximum frame size of 9720 bytes.

The BCM53158XUX supports advanced ContentAware [™] processing using a compact field processor (CFP). Up to four intelligent ContentAware processes are performed in parallel for every packet. This flexible engine uses TCAM-based architecture which allows wildcard capabilities. Action examples include dropping, changing the forward port map, adding forward port, assigning the priority of a frame, and so on. These advanced ContentAware processes are well suited for access control lists (ACLs) and DoS prevention.

An integrated address management engine provides address learning and recognition functions at maximum frame rates. The address table provides capacity for learning up to 16K unicast addresses. Addresses are added to the table after receiving an error-free packet.

The MIB statistics registers collect receive and transmit statistics for each port and provide direct hardware support for the EtherLike-MIB, MIB II (interfaces), and the first four groups of the RMON MIB. All nine groups of RMON can be supported by using additional capabilities, such as port mirroring/snooping, together with an external microcontroller to process some MIB attributes. The MIB registers can be accessed through the Serial Peripheral Interface Port by an external microcontroller.

1.2 Target Markets

The BCM53158XU series targets four main markets:

- SMB Capacity requirement in this market is steadily growing. While 1GE is currently the prominent connectivity speed (about 55% of all links in the SMB), 2016 is the year in which 10GE connectivity is expected to reach the SMB market as well. The BCM53158XU was designed to support this market segment by providing 1GE connectivity toward the SMB customers' end nodes and 2.5GE/10GE connectivity toward the WAN.
- Service Provider The BCM53158XU is focused on two sub-segments within the Service Provider market: 10G G/EPON MDU ONUs and 10GE small-cells. The first sub-segment mentioned is expected to drive the next cycle of growth in embedded connectivity. The BCM53158XUis designed to complete G/EPON chip-sets in ONU and design and deliver a cost effective and high-speed solution. The series is also designed to be used as an embedded component within a small-cell design as they are upgraded to 2.5GE and 10GE connection.

1.3 Operational Mode

BCM53158XU devices support Unmanaged Mode (U) operational modes.

■ Unmanaged mode (U) – This mode should be used by customers who would like to build the most basic switching platform with a single bridging domain, no support for virtual LANs, that is, IEEE 802.1Q VLANS and no ability to rate limit incoming or outgoing traffic. This unmanaged mode does provide customers with 8 traffic classes per port, a default 1:1 mapping between incoming traffic VLAN priority bits and those queues (p-bits with value X will be mapped to queue X+1) and default WRR scheduling weights for improved scheduling of traffic from the queues (the weights are 1:1:2:2:4:4:8:8).

In this mode, the device is shipped to customers with a basic out-of-the-box configuration that activates the switch in a single, no VLAN support, bridging domain. This basic configuration is available on the device's internal ROM and no additional memory is required. However, customers can get additional functionality to that mentioned above by using an external flash and downloading BRDCM's Advanced Unmanaged software. This software supports, in addition to the basic functionality, Auto-Loopdetect, Auto-Dos, and Auto-VoIP functionality, autoQos, and auto IGMP snooping that are further explained here. This mode is termed "Advanced Unmanaged." Note that this mode is not offered separately from the regular Unmanaged mode (U) as it mainly requires that the end user deploy external flash for additional memory.

Table 1: BCM53158XU Operational Modes

Layer	Feature	Unmanaged (U) (* = Features Requires Flash)
er)	Processor	Integrated M7 CPU
Power)	ROM memory for image and config	Internal ROM + Flash
		Flash is necessary
\ar	Operating System	Bare Metal
System Basic Software,	Software Format Delivered to Customers	Binary Code
ysto	SDK Support	✓
		Initialization RSDK
ריסנ	Direct Register Access Support	✓
Леп	Packet Memory	1 MB
(CPU, Memory,	CPU Memory	8 KB
	Cable Diagnostic	√ *
	Cascading	√ *
2	EEE power saving (IEEE 802.3az) ^a	✓
-	AVS3	√*
	Link Aggregation (LAG)	×

Table 1: BCM53158XU Operational Modes

Layer	Feature	Unmanaged (U) (* = Features Requires Flash)
	Jumbo Frames	✓ (9720)
	Switching/MAC Learning	✓ (16K)
	Broadcast Storm Control	√ *
	VLAN support (multiple bridging domains)	×
70	VLAN translation	*
L2 Forwarding	Isolation group (tree)	×
var	Ingress Mirroring	×
ح	Egress Mirroring	×
-2 F	Traffic Sampling	×
1	CFP support (ACLs)	×
	AutoLoop	√ *
	AutoVOIP	√ *
		(256 SA)
	AutoDOS	√ *
	Queues per port	8
	IEEE 802.1p Priority mapping	√ *
	, , , , , ,	Through AutoQoS – mapping is fixed
	DSCP priority mapping	√ *
		Through AutoQoS – mapping is fixed
	Scheduling configurable SP	√ *
တ္		Through AutoQoS
L2 QoS	Scheduling configurable WRR	√ *
L2		Through AutoQoS - Weights are configurable
	Metering Rate Limiting	×
	Shaping queue/port	×
	Hierarchical Shaping	×
	Flow Control – PAUSE IEEE 802.3x	√ *
	Flow Control – PFC IEEE 802.1QBB	√ *
nt	Debug CLI	✓
me	RESTful API	×
Management	Rx and Tx Counters	×
Multicast	IGMP Snooping	√ *
	LLDP	×
Ductossis		
Protocols and	Rapid Spanning Tree	×
Protocols and Advanced	Rapid Spanning Tree Cisco MAC-in-MAC	x x

Table 1: BCM53158XU Operational Modes

Layer	Feature	Unmanaged (U) (* = Features Requires Flash)
to	IEEE 802.1AS (subset of 1588) – One Step	×
Support	IEEE 802.1AS (subset of 1588) – Two Steps	×
ns (IEEE 802.1Qbv (enhancements ftraffic scheduling)	×
(TSN)	IEEE 802.1Qcc (Stream Reservation Protocol –SRP, HW support)	×
ing	Cut-Through mode	×
Š	IEEE 802.1Qav (TSN Forwarding and Queuing)	×
Time-Sensitive Networking	AVB (class A and class B)	×

a. When EEE is enabled (EEE feature is for GPHY port only), the cut-through latency time is impacted causing very high latency (tens of microsceonds). The selection of either EEE or cut-through does not impact performance since both are not available.

1.4 BCM53158XU Devices

The BCM53156X/BCM53158X is a 8xGE + 1 QSGMII Switch with 10GE/2.5GE/1GE uplinks. See the full SKU list in Section 12: "Ordering Information," on page 106.

The BCM53158XU devices are offered in one 13×13 mm² package with 311 pins.

Table 2 provides a detailed list of the physical characteristics for each device in the BCM53158XU family of switches.

Table 2: BCM53158XU Family Features

Features	BCM53158XU
RGMII (port 14)	1
GPHY (ports 0 through 7) 10/100/BASE-T	0
GPHY (ports 0 through 7) 10/100/1000BASE-T	8
SGMII (ports 8 through 11) 100/1000BASE-FX/2500BASE-FXF	0
QSGMII (ports 8 through 11)	1
XFI (ports 12 through 13) 2.5GE/1GE	0
XFI (ports 12 through 13) 10GE/2.5GE/1GE	2
MDIO	1
SPI	3 (QSPI+2SP)
LED (28 pins)	N/A
LED (2 pins) ^a	Serial
JTAG (w/ 2 jtce)	1
1588	No
SyncE	Yes
I ² C	7
MFIO	9
WB-FBGA	13x13 mm ²
Package	0.65 mm
	pitch
	311 balls
PCB Layers	4
Weight	511 mg
Ambient Temp ^b	0°C to 70°C

a. Serial LED uses two bits from the 28-bit parallel LED. Both cannot be active at the same time.

b. 0°C to 70°C for commercial SKUs; –40°C to +85°C for industrial SKUs.

1.5 System Functional Blocks

1.5.1 Overview

The BCM53158XU includes the following blocks:

- Media Access Controller
- Integrated 10/100/1000 PHY
- Interdevice Interface
- MIB Engine
- Integrated High-Performance Memory
- Robo 2 Switch Core

Each of these blocks is discussed in additional detail in the following sections.

1.5.2 Media Access Controller

The BCM53158XU contains eight 10/100/1000 MACs, two 1G/2.5G/10G XMACs, and four 10/100/1000/2.5G MACs.

The MAC automatically selects the appropriate speed (CSMA/CD or full-duplex) based on the PHY auto-negotiation result. In full-duplex mode, IEEE 802.3x PAUSE frame-based flow control is also determined through auto-negotiation. The MAC is IEEE 802.3, IEEE 802.3u, and IEEE 802.3x-compliant.

1.5.2.1 Receive Function

The MAC initiates frame reception following the assertion of receive data valid indication from the physical layer. The MAC monitors the frame for the following error conditions:

- Receive error indication from the PHY
- Runt frame error if frame is fewer than 64 bytes
- CRC error
- Long frame error if frame is greater than standard max. frame size or 9,720 bytes for jumbo-enabled ports.

NOTE: Frames longer than standard max. frame size are considered oversized frames. When jumbo-frame mode is enabled, only the frames longer than 9,720 bytes are bad frames and dropped.

If no errors are detected, the frame is processed by the switch controller. Frames with errors are discarded. Receive functions can be disabled using register settings.

1.5.2.2 Transmit Function

Frame transmission begins with the switch controller queuing a frame to the MAC transmitter. The frame data is transmitted as received from the switch controller. The transmit controller is responsible for preamble insertion, carrier deferral, collision back-off, and inter-packet gap enforcement.

In 10/100 Mb/s half-duplex mode, when a frame is queued for transmission, the transmit controller behaves as specified by the IEEE 802.3 requirements for frame deferral. Following deferral, the transmitter adds 8 bytes of preamble and SFD to the frame data received from the switch controller. If, during frame transmission, a collision is observed and the collision window timer has not expired, the transmit controller asserts jam and then executes the back-off algorithm. The frame is retransmitted when appropriate. On the 16th consecutive collision, the back-off algorithm starts over at the initial state, the collision counter is reset, and attempts to transmit the current frame continue. Following a late collision, the frame is aborted, and the switch controller is allowed to queue the next frame for transmission.

While in full-duplex mode, the transmit controller ignores carrier activity and collision indication. Transmission begins after the switch controller queues the frame and the 96-bit times of IPG have been observed. Transmit functions can be disabled using register settings.

1.5.2.3 Flow Control

The BCM53158XU implements an intelligent flow-control algorithm to minimize the system impact resulting from traffic congestion. Buffer memory allocation is adaptive to the status of each port's speed and duplex mode, providing an optimal balance between flow management and per-port memory depth. The BCM53158XU initiates flow control in response to buffer memory conditions on a per-port basis.

The MACs are capable of flow control in full-duplex mode.

1.5.2.3.1 10/100 Mb/s Half-Duplex

In 10/100 half-duplex mode, the MAC back-pressures a receiving port by transmitting a 96-bit time jam packet to the port. A single jam packet is asserted for each received packet for the duration of the time the port is in the flow-control state.

1.5.2.3.2 10/100/1000 Mb/s Full-Duplex

Flow control in full-duplex mode functions as specified by the IEEE 802.3x requirements. In the receiver, MAC flow-control frames are recognized and, when properly received, set the flow-control pause time for the transmit controller. The pause time is assigned from the 2-byte pause time field following the pause opcode. MAC control PAUSE frames are not forwarded from the receiver to the switch controller.

When the switch controller requests flow control, the transmit controller transmits a MAC control PAUSE frame with the pause time set to maximum. When the condition that caused the flow control state is no longer present, a second MAC control PAUSE frame is sent with the pause time field set to 0.

1.5.2.3.3 Priority Flow Control

Priority Flow Control (PFC) is a mechanism of conveying the per priority XON/XOFF information for 8 different classes using MAC control frames. Unimac provides the flexibility to program the DA, TYPE, and OPCODE fields for the PFC frames. The PFC feature can be independently enabled inside the MAC and pause should be disabled while PFC is operational to ensure IEEE compliance.

1.5.3 Integrated 10/100/1000 PHY

There are two integrated quad-PHY blocks in the BCM53158XU. For more information see Copper Interface. The following sections describe the operations of the internal PHY block.

1.5.3.1 Encoder

The PHY is the Ethernet transceiver that appropriately processes data presented by the MAC into an analog data stream to be transmitted at the MDI interface, which performs the reverse process on data received at the MDI interface. The registers of the PHY are read using the Programming Interfaces. The following sections describe the operations of the internal PHY block. For additional information, see Copper Interface.

In 10BASE-T mode, Manchester encoding is performed on the data stream that is transmitted on the twisted-pair cable. The multimode transmit digital-to-analog converter (DAC) performs preequalization for 100m of Category 3 cabling.

In 100BASE-TX mode, the BCM53158XU transmits a continuous data stream over the twisted-pair cable. The transmit packet is encapsulated by replacing the first two nibbles of preamble with a start-of-stream delimiter (/J/K codes) and appending an end-of-stream delimiter (/T/R codes) to the end of the packet. The transmitter repeatedly sends the idle code group between packets. The encoded data stream is serialized and then scrambled by the stream cipher block, as described in Stream Cipher. The scrambled data is then encoded into MLT3 signal levels.

In 1000BASE-T mode, the BCM53158XU simultaneously transmits and receives a continuous data stream on all four pairs of the Category 5 cable. Byte-wide data from the transmit data pins is scrambled when the transmit enable is asserted, and the trellis (a PAM-5 symbol on each of the four twisted-pairs) is encoded into a four-dimensional code group and then inserted into the transmit data stream. The transmit packet is encapsulated by replacing the first two bytes of the preamble with a start-of-stream delimiter, and appending an end-of-stream delimiter to the end of the packet. When the transmit error input is asserted during a packet transmission, a transmit error code group is sent in place of the corresponding data code group. The transmitter sends idle code groups or carrier-extend code groups between packets. Carrier extension is used by the MAC to separate packets within a multiple-packet burst and is indicated by asserting the transmit error signal and placing 0Fh on the transmit data pins while the transmit enable is low. A carrier extend error is indicated by replacing the transmit data input with 1Fh during carrier extension.

The encoding complies with the IEEE 802.3ab standard and is fully compatible with previous versions of the Broadcom 1000BASE-T PHYs.

1.5.3.2 Decoder

In 10BASE-T mode, Manchester decoding is performed on the data stream.

In 100BASE-TX mode, following equalization and clock recovery, the receive data stream is converted from MLT3 to serial nonreturn-to-zero (NRZ) data. The NRZ data is descrambled by the stream cipher block, as described later in this document. The descrambled data is then deserialized and aligned into 5-bit code groups. The 5-bit code groups are decoded into 4-bit data nibbles. The start-of-stream delimiter is replaced with preamble nibbles, and the end-of-stream delimiter and idle codes are replaced with 0h. The decoded data is driven onto the MII receive data pins. When an invalid code group is detected in the data stream, the BCM53158XU asserts the MII receive error (RX_ER) signal. RX_ER is also asserted when the link fails, or when the descrambler loses lock during packet reception.

In 1000BASE-T mode, the receive data stream is:

- Passed through the Viterbi decoder
- Descrambled
- Translated back into byte-wide data

The start-of-stream delimiter is replaced with preamble bytes, and the end-of-stream delimiter and idle codes are replaced with 00h. Carrier extend codes are replaced with 0Fh or 1Fh. Decoding complies with IEEE standard IEEE 802.3ab and is fully compatible with previous versions of Broadcom 1000BASE-T PHYs.

1.5.3.3 Link Monitor

In 10BASE-T mode, a link-pulse detection circuit constantly monitors the TRD pins for the presence of valid link pulses.

In 100BASE-TX mode, receive signal energy is detected by monitoring the receive pair for transitions in the signal level. Signal levels are qualified using squelch-detect circuits. When no signal is detected on the receive pair, the link monitor enters the Link Fail state and the transmission and reception of data packets is disabled. When a valid signal is detected on the receive pair for a minimum of 1 ms, the link monitor enters the Link Pass state and the transmit and receive functions are enabled.

Following auto-negotiation in 1000BASE-T mode, the master transceiver begins sending data on the media. The slave transceiver also begins transmitting when it has recovered the master transceiver's timing. Each end of the link continuously monitors its local receiver status. When the local receiver status has been good for at least 1 microsecond, the link monitor enters the Link Pass state, and the transmission and reception of data packets are enabled. When the local receiver status is bad for more than 750 ms, the link monitor enters the Link Fail state and the transmission and reception of data packets are disabled.

1.5.3.4 Digital Adaptive Equalizer

The digital adaptive equalizer removes intersymbol interference (ISI) created by the transmission channel media. The equalizer accepts sampled unequalized data from the analog-to-digital converter (ADC) on each channel and produces equalized data. The BCM53158XU achieves an optimum signal-to-noise ratio by using a combination of feed forward equalization (FFE) and decision feedback equalization (DFE) techniques. Under harsh noise environments, these powerful techniques achieve a bit error rate (BER) of less than 1×10^{-12} for transmissions up to 100m on Category 5 twisted-pair cabling (100m on Category 3 UTP cable for 10BASE-T mode). The all-digital nature of the design makes the performance very tolerant to noise. The filter coefficients are self-adapting to accommodate varying conditions of cable quality and cable length.

1.5.3.5 Echo Canceler

Because of the bidirectional nature of the channel in 1000BASE-T mode, an echo impairment is caused by each transmitter. The output of the echo filter is added to the FFE output to remove the transmitted signal impairment from the incoming receive signal. The echo canceler coefficients are self-adapting to manage the varying echo impulse responses caused by different channels, transmitters, and environmental conditions.

1.5.3.6 Crosstalk Canceler

The BCM53158XU transmits and receives a continuous data stream on four channels. For a given channel, the signals sent by the other three local transmitters cause impairments on the received signal because of near-end crosstalk (NEXT) between the pairs. It is possible to cancel the effect because each receiver has access to the data for the other three pairs that cause this interference. The output of the adaptive NEXT canceling filters is added to the FFE output to cancel the NEXT impairment.

1.5.3.7 Analog-to-Digital Converter

Each receive channel has its own 125 MHz analog-to-digital converter (ADC) that samples the incoming data on the receive channel and feeds the output to the digital adaptive equalizer. Advanced analog circuit techniques achieve the following results:

- Low offset
- High power-supply noise rejection
- Fast settling time
- Low bit error rate

1.5.3.8 Clock Recovery/Generator

The clock recovery and generator block creates the transmit and receive clocks for 1000BASE-T, 100BASE-TX, and 10BASE-T operation.

In 10BASE-T or 100BASE-TX mode, the transmit clock is locked to the 25 MHz crystal input, and the receive clock is locked to the incoming data stream.

In 1000BASE-T mode, the two ends of the link perform loop timing. One end of the link is configured as the master, and the other is configured as the slave. The master transmit and receive clocks are locked to the 25 MHz crystal input. The slave transmit and receive clocks are locked to the incoming receive data stream. Loop timing allows for the cancellation of echo and NEXT impairments by ensuring that the transmitter and receiver at each end of the link are operating at the same frequency.

1.5.3.9 Baseline Wander Correction

1000BASE-T and 100BASE-TX data streams are not always DC-balanced. Because the receive signal must pass through a transformer, the DC offset of the differential receive input can vary with data content. This effect, which is known as baseline wander, can greatly reduce the noise immunity of the receiver. The BCM53158XU automatically compensates for baseline wander by removing the DC offset from the input signal, thereby significantly reducing the probability of a receive symbol error.

In 10BASE-T mode, baseline wander correction is not performed because the Manchester coding provides a perfect DC balance.

1.5.3.10 Multimode TX Digital-to-Analog Converter

The multimode transmit digital-to-analog converter (DAC) transmits PAM-5, MLT3, and Manchester coded symbols. The transmit DAC performs signal-wave shaping that decreases the unwanted high-frequency signal components, reducing electromagnetic interference (EMI). The transmit DAC uses a current drive output that is well-balanced, and therefore, produces very low noise transmit signals.

1.5.3.11 Stream Cipher

In 1000BASE-T and 100BASE-TX modes, the transmit data stream is scrambled to reduce radiated emissions and to ensure that there are adequate transitions within the data stream. The 1000BASE-T scrambler also ensures that there is no correlation among symbols on the four different wire pairs and in the transmit and receive data streams. The scrambler reduces peak emissions by randomly spreading the signal energy over the transmit frequency range and eliminating peaks at certain frequencies. The randomization of the data stream also assists the digital adaptive equalizers and echo/crosstalk cancelers. The algorithms in these circuits require there to be no sequential or cross-channel correlation among symbols in the various data streams.

In 100BASE-TX mode, the transmit data stream is scrambled by exclusive ORing the encoded serial data stream. This is done with the output of an 11-bit wide linear feedback shift register (LFSR), producing a 2047-bit nonrepeating sequence.

In 1000BASE-T mode, the transmit data stream is scrambled by exclusive ORing the input data byte with an 8-bit wide cipher text word. The cipher text word generates each symbol period from eight uncorrelated maximal length data sequences that are produced by linear remapping of the output of a 33-bit wide LFSR. After the scrambled data bytes are encoded, the sign of each transmitted symbol is again randomized by a 4-bit wide cipher text word that is generated in the same manner as the 8-bit word. The master and slave transmitters use different scrambler sequences to generate the cipher text words. For repeater or switch applications, where all ports can transmit the same data simultaneously, signal energy is randomized further by using a unique seed to initialize the scrambler sequence for each PHY.

The receiver descrambles the incoming data stream by exclusive ORing it with the same sequence generated at the transmitter. The descrambler detects the state of the transmit LFSR by looking for a sequence representing consecutive idle code groups. The descrambler locks to the scrambler state after detecting a sufficient number of consecutive idle codes. The BCM53158XU enables transmission and reception of packet data only when the descrambler is locked. The receiver continually monitors the input data stream to ensure that it has not lost synchronization by checking that inter-packet gaps containing idles or frame extensions are received at expected intervals. When the BCM53158XU detects loss of synchronization, it notifies the remote PHY of the inability to receive packets (1000BASE-T mode only) and attempts to resynchronize to the received data stream. If the descrambler is unable to resynchronize for a period of 750 ms, the BCM53158XU is forced into the Link Fail state.

In 10BASE-T mode, scrambling is not required to reduce radiated emissions.

1.5.3.12 Wire Map and Pair Skew Correction

During 1000BASE-T operation, the BCM53158XU has the ability to automatically detect and correct some UTP cable wiring errors. The symbol decoder detects and compensates for (internal to the BCM53158XU) the following errors:

- Wiring errors caused by the swapping of pairs within the UTP cable.
- Polarity errors caused by the swapping of wires within a pair.

The BCM53158XU also automatically compensates for differences in the arrival times of symbols on the four pairs of the UTP cable. The varying arrival times are caused by differing propagation delays (commonly referred to as delay skew) between the wire pairs. The BCM53158XU can tolerate delay skews of up to 64 ns long. Auto-negotiation must be enabled to take advantage of the wire map correction.

During 10/100 Mb/s operation, pair swaps are corrected. Delay skew is not an issue though, because only one pair of wires is used in each direction.

1.5.3.13 Automatic MDI Crossover

During copper auto-negotiation, one end of the link must perform an MDI crossover so that each transceiver's transmitter is connected to the other receiver. The BCM53158XU can perform an automatic media-dependent interface (MDI) crossover, eliminating the need for crossover cables or cross-wired (MDIX) ports. During auto-negotiation, the BCM53158XU normally transmits and receives on the TRD pins.

When connecting to another device that does not perform MDI crossover, the BCM53158XU automatically switches its TRD in pairs when necessary to communicate with the remote device. When connecting to another device that does have MDI crossover capability, an algorithm determines which end performs the crossover function.

During 1000BASE-T operation, the BCM53158XU swaps the transmit symbols on pairs 0 and 1 and pairs 2 and 3 if autonegotiation completes in the MDI crossover state. The 1000BASE-T receiver automatically detects pair swaps on the receive inputs and aligns the symbols properly within the decoder. The automatic MDI crossover function cannot be disabled when in 1000BASE-T mode. During 10BASE-TX and 100BASE-T operation, pair swaps automatically occur within the device and do not require user intervention. The automatic MDI crossover function by default works only when auto-negotiation is enabled. This function can be disabled during auto-negotiation using a register write.

NOTE: This function operates only when the copper auto-negotiation is enabled.

1.5.3.14 10/100BASE-TX Forced Mode Auto-MDIX

The automatic MDI crossover function can also be enabled when in forced 10BASE-T or forced 100BASE-TX mode. This feature allows the user to disable the copper auto-negotiation in either 10BASE-T or 100BASE-TX and still take advantage of the automatic MDI crossover function. Whenever the forced link is down for at least 4 seconds, then auto-negotiation is internally enabled with its automatic MDI crossover function until link pulses or 100TX idles are detected. Once detected, the PHY returns to forced mode operation.

NOTE: This function operates only when the copper auto-negotiation is disabled.

1.5.3.15 PHY Address

The BCM53158XU has eight unique PHY addresses for MII management of the internal PHYs. The PHY addresses for each port are as follows,

- PHY address for Port 0 is 1
- PHY address for Port 1 is 2
- PHY address for Port 2 is 3
- PHY address for Port 3 is 4
- PHY address for Port 4 is 5
- PHY address for Port 5 is 6
- PHY address for Port 6 is 7
- PHY address for Port 7 is 8

1.5.3.16 Super Isolate Mode

When in Super Isolate mode, the transmit and receive functions on the Copper Media Dependent Interface are disabled (no link is established with the PHY's copper link partner). Any data received from the switch is ignored by the BCM53158XU and no data is sent from the BCM53158XU.

1.5.3.17 Standby Power-Down Mode

The BCM53158XU can be placed into standby power-down mode using software commands. In this mode, all PHY functions except for the serial management interface are disabled. There are three ways to exit standby power-down mode:

- Clear MII Control register, bit 11 = 0.
- Set the software RESET bit 15.
- Assert the hardware RESET pin.

Read or write operations to any MII register, other than MII Control register, while the device is in the standby power-down mode returns unpredictable results. Upon exiting standby power-down mode, the BCM53158XU remains in an internal reset state for 40 µs and then resumes normal operation.

1.5.3.18 Auto Power-Down Mode

The BCM53158XU can be placed into auto power-down mode. Auto power-down mode reduces device power when the signal from the copper link partner is not present. The auto power-down mode works whether the device is in Autonegotiation Enabled or Forced mode. This mode is enabled by setting bit 5 =1 of Auto Power-Down register. When auto power-down mode is enabled, the BCM53158XU automatically enters the low-power mode when energy on the line is lost, and it resumes normal operation when energy is detected. The energy-detect circuit is always enabled even when a port is in low-power mode. When the BCM53158XU is in auto power-down mode, it wakes up after 2.7s or 5.4s, which determined by bit 4 of Auto Power-Down register, and sends link pulses to the link partner. The BCM53158XU enters normal operation and establishes a link if energy is detected.

NOTE: Auto power-down mode is a Broadcom proprietary feature and is based on IEEE standard.

1.5.3.19 External Loopback Mode

The External Loopback mode allows in-circuit testing of the BCM53158XU as well as the transmit path through the magnetics and the RJ-45 connector. External loopback can be performed with and without a jumper block. External loopback with a jumper block tests the path through the magnetics and RJ-45 connector. External loopback without the jumper block tests only the BCM53158XU's transmit and receive circuitry. In 1000BASE-T, 100BASE-TX, and 10BASE-T modes, a jumper block must be inserted into the RJ-45 connector to support external loopback. The jumper block should have the following RJ-45 pins connected together:

1-----3 2------6 4-----7 5-----8

The following six tables describe how the external loopback is enabled for 1000BASE-T, 100BASE-TX, and 10BASE-T modes with and without a jumper block.

Table 3: 1000BASE-T External Loopback with External Loopback Plug

Register Writes	Comments
Write 1800h to 1000BASE-T Control register	Enable 1000BASE-T Master Mode
Write 0040h to MII Control register	Enable Force 1000BASE-T
Write 8400h to Auxiliary Control register	Enable External Loopback Mode with external loopback plug

Table 4: 1000BASE-T External Loopback Without External Loopback Plug

Register Writes	Comments
Write 1800h to 1000BASE-T Control register	Enable 1000BASE-T Master Mode
Write 0040h to MII Control register	Enable Force 1000BASE-T
Write 8400h to Auxiliary Control register	Enable External Loopback Mode
Write 0014h to Auxiliary Control register	Enable External Loopback Mode without external loopback plug

Table 5: 100BASE-TX External Loopback with External Loopback Plug

Register Writes	Comments
Write 2100h to MII Control register	Enable Force 100BASE-TX full-duplex mode

Table 6: 100BASE-TX External Loopback Without External Loopback Plug

Register Writes	Comment
Write 2100h to MII Control register	Enable Force 100BASE-TX full-duplex mode
Write 0014h to Auxiliary Control register	Enable external loopback mode without external loopback plug

Table 7: 10BASE-T External Loopback with External Loopback Plug

Register Writes	Comments
Write 0100h to MII Control register	Enable Force 10BASE-T full-duplex mode

Table 8: 10BASE-T External Loopback Without External Loopback Plug

Register Writes	Comments
Write 0100h to MII Control register	Enable Force 10BASE-T full-duplex mode
Write 0014h to Auxiliary Control register	Enable external loopback mode without external loopback plug

NOTE: To exit the External Loopback mode, a software or hardware reset is recommended.

1.5.3.20 Full-Duplex Mode

The BCM53158XU supports full-duplex operation. While in full-duplex mode, a transceiver can simultaneously transmit and receive packets on the cable.

1.5.3.20.1 Copper Mode

When auto-negotiation is disabled, full-duplex operation can be enabled using register settings.

When auto-negotiation is enabled, the full-duplex capability is advertised for one of the following, depending on the register settings:

- 10BASE-T
- 100BASE-T
- 1000BASE-T

1.5.3.21 Master/Slave Configuration

In 1000BASE-T mode, the BCM53158XU and its link partner perform loop timing. One end of the link must be configured as the timing master, and the other end as the slave. Master/slave configuration is performed by the auto-negotiation function. The auto-negotiation function first looks at the manual master/slave configuration bits advertised by the local PHY and the link partner. If neither PHY requests manual configuration, then the auto-negotiation function looks at the advertised repeater/DTE settings. If one PHY is advertised as a repeater port and the other is advertised as a DTE port, then the repeater port is configured as the master and the DTE port as the slave. Each end generates an 11-bit random seed if the two settings are equal, and the end with the higher seed is configured as the master. If the local PHY and the link partner generate the same random seed, then auto-negotiation is restarted.

If both ends of the link attempt to force the same manual configuration (both master or both slave), or the random seeds match seven consecutive times, then the BCM53158XU sets the Master/Slave Configuration Fault bit in the 1000BASE-T Status register, and auto-negotiation is restarted. This is used to set the BCM53158XU to manual master/slave configuration or to set the advertised repeater/DTE configuration.

1.5.3.22 Next Page Exchange

The 1000BASE-T configuration requires the exchange of three auto-negotiation next pages between the BCM53158XU and its link partner. Exchange of 1000BASE-T Next Page information takes place automatically when the BCM53158XU is configured to advertise 1000BASE-T capability.

The BCM53158XU also supports software controlled Next Page exchanges. This includes the three 1000BASE-T Next Pages, which are always sent first. The BCM53158XU automatically generates the appropriate message code field for the 1000BASE-T pages. When the BCM53158XU is not configured to advertise 1000BASE-T capability, the 1000BASE-T Next Pages are not sent.

When the BCM53158XU is not configured to advertise 1000BASE-T capability, the BCM53158XU does not advertise Next Page ability.

1.5.3.23 XLMAC

XLMAC is used for the implementation of 10G Ethernet layer for the BCM53158XU. The XLMAC core is designed as a single module, supporting four 10G/2.5G/1G/100M/10M MACs. The basic idea is to have a single core optimized for multi-lane operation to save area and power.

1.5.4 Interdevice Interface

The BCM53158XU can connect to two types of external devices: another BCM53158XU (cascade) and/or and external processor (CP). The information required for these two application is similar and uses a common header.

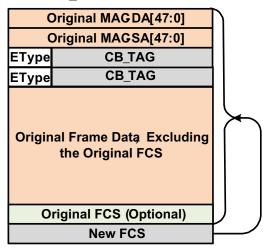
The processor can be connected to any port including the internal processor. In Robo terminology, this port is designated as an IMP (internal management port). Frames that are sent to these destinations use the same forwarding rules as any other destination, for example DLIs. There are various ways frames can be directed to each of these destinations including the CFP, ARL, and various filters. Part of the DLI instruction could be to insert the CB tag which provides additional information to aid in processing the frames.

There is one type of IMP header designs which the BCM53158XU supports: CB TAG – 8B CB tag which is inserted directly after the MAC-SA

- This format is parseable via the CT-TAG Ethertype.
- This format might include an optional timestamp with a separate Ethertype.

Figure 2: IMP/CB Header Formats

CB_TAG Header



The following rules and guidelines are used for:

- All frames on a cascade port will carry the CB tag.
- Traffic on the IMP port may or may not have the CB tag.
- Normal processing (for example, a port is the destination of the frame) can be sent without a tag.
- When a CB receives a frame with a CB_TAG, the SPG, SLI, and VSI are reconstituted based on information in the tag. It is presented to the ARL lookups as if the frame was processed by the receive logic.
- There are few exceptions to this i.e. traps, mirroring and directed forwarding.
- After the tag is parsed it is removed.

NOTE: For unicast, multicast, traps, and exception forwarding, it is intended that the source information (SPG, LIN, VSI) is populated in the receive header. This enables the CPU to use this in processing to determine the how to forward the frame. In addition, it is expected the CPU properly sets these fields when it sends a frame to the switch which is sent out.

The Switch to CP and CP to Switch tag formats are purposely defined to be consistent across the IMP and Cascade modes. The forwarding codes (fwd_op) are defined to allow the hardware to interpret the intended function from the code point regardless of the specific IMP or Cascade type in most cases.

1.5.4.1 Switch to Control Plane: CB Tag

This tag is used to communicate information to an attached CPU or cascaded BCM53158XU. The format and fields are defined in the following tables. The tag is attached to frames using editing directives. The directive could be associated with a port (PET table) or DLI. The Ethertype for this tag is taken from a configuration register. The format and fields are defined in Table 9.

Table 9: Switch to CB TAG Format

15	14	13	12	11	10	09	08	07	06	05	04	03	02	01	00
				Ethertype											
	TC		D	P FWD_OP DEV LBH/TRAP_GROUP/SPP/DPP					PP						
	DI	EST[11:0)] - deper	ids on FWD_OP {for example, DLLI/DG/EXCEPTION} R R SPG					G						
	SPG		Т		N_VSI [11:0] (VSI or LIN based on T)										

Table 10: Switch to CP Header Format Fields

Field	Function
Ethertype	Configured value
TC	TC value classified for the packet by the switch
DP	Discard precedence
DEV	Source device identifier; configured by software
SPG	Source Port Group – SPG determined for the frame
FWD_OP	Forwarding Operation – see table
Т	LIN Type indicator. 0 is LIN, 1 is PV format
N_VSI	Source Local Logical Interface: If T = 1 (type PV), SLLI = {1,0,SPG}; VSI=N_VSI else(type LIN) SLLI={0,N_VSI}; VSI=LIN2VSI(N_VSI);
DEST - overlay	Overlay field with one of the following depending on FWD_OP
DLLI	Destination Logical Local Interface: If FWD_OP = UNICAST
DG	Destination Group (multicast/broadcast): If FWD_OP = MULTICAST
EXCEPTION	Exception – Identifies the reason a trap was triggered (TRAP, SLIC, CFP): If FWD_OP = TRAP
LBH - overlay	Trap Group/Load Balancing Hash: If FWD_OP=TRAP, TRAP_GROUP else LBH
LBH	Load balancing hash- Valid for all op codes except 2
Trap_group	Trap group for the SLICT and CFP traps in FWD_OP=2
SPP	Source Physical Port for traps (FWD_OP=2)
DPP	Destination Physical Port
RSVD	Reserved – write as zero, ignore on receipt

The forwarding operation (FWD_OP) field defines the content of the DEST field and provides information to the CPU regarding why the frame was delivered. The DEST field in the header is overlay with number of meanings summarized in the following table.

Table 11: IMP Header Forwarding Operation: Switch to CP

FWDOP	Function	DEST	LRN?	TG/LBH/SPP	Notes – processing at EPP
0	CP Directed Forwarding	0	No	DPP	Frame is directly sent on port specified by LBH/DPP field.
0	Unicast Directed Forwarding	DLLI	Yes	LBH	Unicast forwarding with known destination, that is, the DLI. The SPG, N_VSI, and T fields are used to reconstitute the SLI for the frame before the ARL Source lookup is done.
1	Multicast Directed Forwarding	DG	Yes	LBH	Multicast forwarding with known destination i.e. DG. The SPG, N_VSI, and T fields are used to reconstitute the SLI for the frame before the ARL Source lookup is done.
2 ^a	SA Learn	SA_LRN (trap_id)	Yes	LBH	Learning message: This is generated based on SA Miss in the source device ARL lookup. The SPG, T and N_VSI are used to in the ARL lookup. This is converted to CA_SA_LRN trap.
2 ^a	SA Move	SA_MOVE (trap_id)	Yes	LBH	SA Move message: This is generated based on SA move in the source device ARL lookup. The SPG, T and N_VSI are used to in the ARL lookup. This is converted to CA_SA_LRN trap.
2 ^a	Mirror	128-191 (mirror_ld)	No	LBH	This is a copy generated due to mirroring, the mirror id is extracted from the DEST and the MTGT is used to determine how the frame is handled.
2 ^a	Trap	1-127 (trap_id)	No	SPP	This is a copy generated due to a trap condition. The trap_id is extracted from the DEST field and the TCT table will govern the handling of this frame.
2 ^a	SLIC_TRAP	256-511 (slic_trap)	No	Trap_group	This is a copy generated due to a SLIC trap condition. The trap_group is extracted from the LBH field and the MTGT table is use to determine how the frame is handled.
2 ^a	CFP_TRAP	2048-3071 (action_idx)	No	Trap_group	This is a copy generated due to a CFP trap condition. The trap_group is extracted from the LBH field and the MTGT table is use to determine how the frame is handled.
2 ^a	NULL TAG	0x0	Yes	Х	NOP TAG – CB tag is removed and processed as if it arrived on the CPU port (backwards compatibility so all frames can have a tag), This use and unused trap_group code point.
3–7	Reserved	n/a	n/a	Na/	Reserved for future use.

a. For FWD_OP = 2 the DEST is defined as an EXCEPTION following the encoding shown in Figure 24.

Here are some notes on processing frames at the CPU/Cascaded Device:

- The CB tag is removed on ingress.
- If fwd_op = 0x0 and DLLI is zero, a valid destination was not determined by the switch (DLF destination lookup failure).
- Flooding uses a multicast forwarding with a zero DG. In this case, the flooding map (pg_map) comes from the VSIT based on the VSI in the frame (or LIN2VSI).
- Multicast is handled by used the DG as multicast group.
- For FWD_OP = 2 the encoding the DEST field is used to identify the type of frame (SA-Learn, Mirror, TRAP). The encoding follows the EXCEPTION space shown in Figure 24.
- The DEV field must be preserved if the frame is sent to a CPU with CB_TAG. This allows the CPU to determine which of the two devices the originated exception frame.
- SA learning and SA movement traps are converted to cascaded version of the trap and the {vsi, smac} is inserted in the ARL table if possible.
- Mirror implies the frame was mirrored or sampled; the mirror_group is extracted from the DEST field and the mirror is handled group gives further information or will be used by a cascaded BCM53158XU to process the mirror.
- SA learn packets will be locally learned and converted to local cascaded traps for cascade processing.

■ The trap packet uses the trap_group to process the frame. Note this is the only format that has a SPP versus a SPG.

1.5.4.2 Switch to Control Plane: Time Stamp Tag

This section describes the tag used from the switch to CPU to send the time stamp. This tag is added using an egress editing directive. The format and fields are defined in the following tables. The Ethertype for this tag is taken from a configuration register.

Table 12: Egress CB TS Tag

15	14	13	12	11	10	09	08	07	06	05	04	03	02	01	00
	Ethertype														
	TIMESTAMP[47:32]														
	TIMESTAMP[31:16]														
	TIMESTAMP[15:0]														

The Ethertype is taken from a software configured register. Timestamp is the 48 bit value sampled at Start of Packet when the frame arrived.

1.5.4.3 Control Plane to Switch: CB Tag

This section describes the tag used from the Control Plane to Switch. The fields are the same as the Switch to CP format described above. Normal frame processing (Unicast, Multicast, and Flooding) rely on the SPG, T and N_VSI field being set properly by the CPU. As noted before, this fields will be valid for frames received by the CPU. It is therefore possible, to direct this frame to a DLI by simply populating the DLI, FWD_OP and sending the frame back into the switch using this format. The following notes apply to sending frames from the CPU:

- To send a Unicast frame out a port group; Frame learned by ARL and egress edits ARE applied:
 - Set FWD OP=0 to Unicast Directed Forwarding
 - Set DEST = DLLI frame will be forwarded based specified DLI
 - Set T, SPG, N VSI frame will be learned in this context
- To send a Unicast frame out a physical port without any checks (VLAN membership, STP, or filters); Frame is not learned by ARL and egress edits ARE NOT applied:
 - Set FWD OP=0 to Unicast Directed Forwarding
 - Set DEST = 0
 - Set LBH/DPP field to desired port (DPP); Note this is the only format that has a DPP vs DPG.
- To send a frame to a multicast group:
 - Set FWD OP=1 to Multicast Directed Forwarding;
 - Set DEST to DG frame will be forwarded based specified DLI
 - Set T, SPG, N_VSI the SLLID to SLLID for frame will be derived from these fields for source port knock-out.
- To send a frame and have the switch forward the frame; Frame is learned by ARL:
 - Send the frame without the IMP/CP tag

1.5.5 MIB Engine

The MIB Engine is responsible for processing status words received from each port. Based on whether it is a receive status or transmit status, appropriate MIB counters are updated. The BCM53158XU implements 66 MIB counters on a per-port basis. MIB counters can be categorized into three groups: receive-only counters, transmit-only counters, and receive or transmit counters. This latter group can, as a group, be selectively steered to the receive or transmit process on a per-port basis. The section below describes each individual counter.

The BCM53158XU offers the MIB snapshot feature per port. A snapshot of a selected port MIB registers can be captured and available to the users while MIB counters are continuing to count.

1.5.5.1 MIB Counters

All counters can be read/write access. The reset values are all zero.

Table 13: Receive MIB Counters (per port)

Receive Counter	Width	Description
RxDropPkts	32	Number of good packets received by a port that were dropped due to a lack of resources (for example, lack of input buffers) or were dropped due to a lack of resources before a determination of the validity of the packet was able to be made (for example, receive FIFO overflow). The counter is only incremented if the receive error was not counted by the RxExcessSizeDisc, the RxAlignmentErrors, or the RxFCSErrors counters.
RxOctets	64	Number of data bytes received by a port (excluding preamble, but including FCS), including bad packets.
RxBroadcastPkts	32	Number of good packets received by a port that are directed to the broadcast address. This counter does not include errored broadcast packets or valid multicast packets. The maximum packet size can be programmed.
RxMulticastPkts	32	Number of good packets received by a port that are directed to a multicast address. This counter does not include errored multicast packets or valid broadcast packets. The maximum packet size can be programmed.
RxSAChanges	32	Number of times the SA of good receive packets has changed from the previous value. A count greater than 1 generally indicates the port is connected to a repeater-based network. The maximum packet size can be programmed.
RxUndersizePkts	32	Number of good packets received by a port that are less than 64 bytes long (excluding framing bits, but including the FCS).
RxOversizePkts	32	Number of good packets received by a port that are greater than standard max frame size. The maximum packet size can be programmed.
RxFragments	32	Number of packets received by a port that are less than 64 bytes (excluding framing bits) and have either an FCS error or an alignment error.
RxJabbers	32	Number of packets received by a port that are longer than standard max frame size and have either an FCS error or an alignment error.
RxUnicastPkts	32	Number of good packets received by a port that are addressed to a unicast address. The maximum packet size can be programmed.
RxAlignmentErrors	32	Number of packets received by a port that have a length (excluding framing bits, but including FCS) between 64 and standard max frame size, inclusive, and have a bad FCS with a nonintegral number of bytes.
RxFCSErrors	32	Number of packets received by a port that have a length (excluding framing bits, but including FCS) between 64 and standard max frame size inclusive, and have a bad FCS with an integral number of bytes.
RxGoodOctets	64	Total number of bytes in all good packets received by a port (excluding framing bits, but including FCS). The maximum packet size can be programmed.
JumboPktCount	32	Number of good packets received by a port that are greater than the standard maximum size and less than or equal to the jumbo packet size, regardless of CRC or alignment errors.

Table 13: Receive MIB Counters (per port) (Continued)

Receive Counter	Width	Description
RxPausePfcPkts	32	When PAUSE is configured: This counter counts the number of PAUSE frame on the port. When the port is configured in PFC mode it counts the number of PFC frames.
		Number of PAUSE frames received by a port. The PAUSE frame must have a valid MAC Control Frame EtherType field (88–08h), have a destination MAC address of either the MAC Control frame reserved multicast address (01-80-C2-00-00-01) or the unique MAC address associated with the specific port, a valid PAUSE opcode (00–01), be a minimum of 64 bytes in length (excluding preamble but including FCS), and have a valid CRC. Although an IEEE 802.3-compliant MAC is only permitted to transmit PAUSE frames when in full-duplex mode with flow control enabled and with the transfer of PAUSE frames determined by the result of auto-negotiation, an IEEE 802.3 MAC receiver is required to count all received PAUSE frames, regardless of its half/full-duplex status. An indication that a MAC is in half-duplex with the RxPausePkts incrementing indicates a noncompliant transmitting device on the network.
RxSymbolErrors	32	Total number of times a valid-length packet was received at a port and at least one invalid data symbol was detected. The counter only increments once per carrier event and does not increment on detection of a collision during the carrier event.
RxDiscard	32	Number of good packets received by a port that were discarded by the Forwarding Process. This would include any shaping or DOS filters.
RxPkts64Octets	32	Number of packets received (including error packets) that are 64 bytes long.
RxPkts65to127Octets	32	Number of packets received (including error packets) that are between 65 and 127 bytes long.
RxPkts128to255Octets	32	Number of packets received (including error packets) that are between 128 and 255 bytes long.
RxPkts256to511Octets	32	Number of packets received (including error packets) that are between 256 and 511 bytes long.
RxPkts512to1023Octet s	32	Number of packets received (including error packets) that are between 512 and 1023 bytes long.
RxPkts1024toMaxPktO ctets	32	Number of packets received (include error packets) that are between 1024 and the standard maximum packet size inclusive.

Table 14: Transmit MIB Counters

TxOctets 64 Tota FCS TxBroadcastPkts 32 Num	counter is incremented every time a transmit packet is dropped due to lack of urces (for example, transmit FIFO underflow), or an internal MAC sublayer transmit not counted by either the TxLateCollision or the TxExcessiveCollision counters. I number of good bytes of data transmitted by a port (excluding preamble but including). ber of good packets transmitted by a port that are directed to a broadcast address. This
TxBroadcastPkts 32 Num).
	her of good packets transmitted by a port that are directed to a broadcast address. This
coun	ter does not include errored broadcast packets or valid multicast packets.
	ber of good packets transmitted by a port that are directed to a multicast address. This ter does not include errored multicast packets or valid broadcast packets.
TxCollisions 32 Num	ber of collisions experienced by a port during packet transmissions.
TxUnicastPkts 32 Num	ber of good packets transmitted by a port that are addressed to a unicast address.
TxSingleCollision 32 Num collis	ber of packets successfully transmitted by a port that have experienced exactly one ion.
TxMultipleCollision 32 Num collis	ber of packets successfully transmitted by a port that have experienced more than one ion.
beca	ber of packets transmitted by a port for which the first transmission attempt is delayed use the medium is busy. This only applies to the Half Duplex mode, while the Carrier sor Busy.
TxLateCollision 32 Num a page	ber of times that a collision is detected later than 512 bit-times into the transmission of cket.
	ber of packets that are not transmitted from a port because the packet experienced 16 mission attempts.
	ber of PAUSE control frames sent when the port is configured in PAUSE mode. In PFC e, it counts the number of PFC frames sent.
lack attrib requ	ber of valid packets received which are discarded by the forwarding process due to of space on an output queue (not maintained or reported in the MIB counters). This pute only increments if a network device is not acting in compliance with a flow control est or the ROBO GE Switchcore internal flow-control/buffering scheme has been gured incorrectly.
	number of good packets transmitted on COS0, which is specified in MIB queue select ter when QoS is enabled.
	number of good packets transmitted on COS1, which is specified in MIB queue select ter when QoS is enabled.
	number of good packets transmitted on COS2, which is specified in MIB queue select ter when QoS is enabled.
	number of good packets transmitted on COS3, which is specified in MIB queue select ter when QoS is enabled.
	number of good packets transmitted on COS4, which is specified in MIB queue select ter when QoS is enabled.
	number of good packets transmitted on COS5, which is specified in MIB queue select ter when QoS is enabled.

Table 14: Transmit MIB Counters (Continued)

Transmit Counter	Width	Description
TxQ6PKT	32	Total number of good packets transmitted on COS6, which is specified in MIB queue select register when QoS is enabled.
TxQ7PKT	32	Total number of good packets transmitted on COS7, which is specified in MIB queue select register when QoS is enabled.
TxPkts64Octets	32	Number of transmitted packets (including error packets) that are 64 bytes long.
TxPkts65to127Octets	32	Number of transmitted packets (including error packets) that are between 65 and 127 bytes long.
TxPkts128to255Octets	32	Number of transmitted packets (including error packets) that are between 128 and 255 bytes long.
TxPkts256to511Octets	32	Number of transmitted packets (including error packets) that are between 256 and 511 bytes long.
TxPkts512to1023Octets	32	Number of transmitted packets (including error packets) that are between 512 and 1023 bytes long.
TxPkts1024toMaxPktOctets	32	Number of transmitted packets that (include error packets) are between 1024 and the standard maximum packet size inclusive.

1.5.6 Integrated High-Performance Memory

The BCM53158XU embeds a high-performance SRAM for storing packet data and associated metadata.

The integrated memory is 1 MB and can be flexibly partitioned into a packet buffer region, and a region available to the M7/8051 for instruction/data memory as well as storage for packets forwarded to the CPU (UM mode is restricted by OTP to only 128 KB of the 1 MB of memory). The BCM53158XU M7 processor also has 32 KB ITCM, 64 KB DCTM, 16 KB I-Cache, and 16 KB D-Cache.

In addition, instead of the IVM and EMV, the following tables exist:

- Logical Interface Mapper (LIM): 2K entry hash table to support virtual ports and double-tagged frames, etc.
- VSI Tag Control (VTC): 4K entry with per port controls for egress edits

This eliminates the need for external memory and allows for the implementation of extremely low-cost systems.

The internal RAM controller efficiently executes memory transfers and achieves nonblocking performance for stand-alone 8-port applications and for applications with up to 15 ports and 33 Gb/s throughput.

1.5.7 Robo 2 Switch Core

The core of the BCM53158XU devices is a cost-effective and high-performance switch controller. The controller manages packet forwarding between the MAC receive and transmit ports through the frame buffer memory with a store and forward architecture. The switch controller encompasses the functions of buffer management, memory arbitration, and transmit descriptor queuing.

1.5.7.1 Buffer Management

The frame buffer memory is divided into pages (units of data consisting of 256 bytes each). Each received packet may be allocated more than one page. For example, six pages are required to store a 1522-byte frame. Frame data is stored in the buffer memory as the packet is received. After reception, the frame is queued to the egress port(s) transmit queue. This list tracks the transmission of the packet. After successful packet transmission, the buffer memory is released to the free buffer pool.

1.5.7.2 Memory Arbitration

Processes requesting access to the internal memory include the receive and transmit frame data handlers, egress descriptor update, and output-port queue managers. These processes are arbitrated to provide fair access to the memory and minimize the latency of critical processes to provide a fully nonblocking solution.

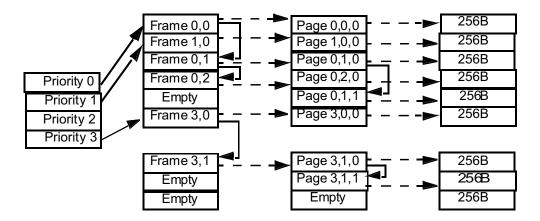
1.5.7.3 Transmit Output Port Queues

Frames are maintained in the egress port using a linked list. Two levels of linked lists are used to maintain one output queue (see Figure 3). The first level is the TXQ linked list, and the second level is the buffer tag linked list. The TXQ linked list is used to maintain frame TC order for each port. For each frame, the buffer tag linked list is used to maintain the order of the buffer pages corresponding to each frame.

Each egress port supports up to eight transmit queues for servicing Quality of Service (QoS). All eight transmit queues share the all entries of the TXQ table. The TXQ table is maintained as a linked list, and each node in the TXQ uses one entry in the TXQ table.

When the QoS function has been turned off, the switch controller maintains one output queue for each egress port. The TXQ table is maintained in a per-port individual internal memory. Each node in the queue represents a pointer that points to a frame buffer tag. Each buffer tag includes frame information and a pointer to the next buffer tag. Each buffer tag has an associated page allocated in the frame buffer. For a packet with a frame size larger than 256 bytes, multiple buffer tags are required. For instance, a 9720-byte jumbo frame requires 38 buffer tags for handling the frame.

Figure 3: TXQ and Buffer Tag Structure



1.6 Notational Conventions

The following notational conventions are used in this document:

- Signal names are shown in uppercase letters (such as DATA).
- A bar over a signal name indicates that it is active low (such as CE).
- In register and signal descriptions, [n:m] indicates a range from bit n to bit m (such as [7:0] indicates bits 7 through 0, inclusive).
- The use of R or Reserved indicates that a bit or a field is reserved by Broadcom for future use. Typically, R is used for individual bits and Reserved is used for fields.
- Numerical modifiers such as K or M follow traditional usage (for example, 1 KB means 1,024 bytes, 100 Mb/s [referring to fast Ethernet speed] means 100,000,000 b/s, and 133 MHz means 133,000,000 Hz).

Chapter 2: Features and Operation

2.1 Overview

The BCM53158XU switches include the following features:

- ARM Cortex-M7 Core
- Software Reset
- Jumbo Frame Support
- AutoDOS
- AutoVOIP
- AutoQoS
- Auto LoopDetect
- Auto IGMP Snooping
- Cascading
- Cable Diagnosis
- Power-Saving Modes

The following sections discuss each feature in more detail.

2.2 ARM Cortex-M7 Core

The BCM53158XU integrates a low-power and high-performance ARM Cortex-M7 processor core with a clock speed of up to 400 MHz. The ARM Cortex-M7 core includes integrated 16 KB two-way set-associative I-Cache and 16 KB four-way set-associative D-Cache. The BCM53112/BCM5315X/BCM5316X also supports a 32 KB ITCM and 64 KB DTCM.

2.3 Software Reset

The BCM53158XU provides software resets. Software resets can be triggered by setting the register.

NOTE: Software reset sets all the register to the default values. Software reset does not latch in the strap pin values, but the previous latched strap pin values are retained.

2.4 Jumbo Frame Support

The BCM53158XU can receive and transmit frames of extended length on ports linked at Gigabit speed. Referred to as jumbo frames, these packets are longer than the standard maximum size, but shorter than 9728 bytes.

Jumbo packets can be received or forwarded to 1000BASE-T, and 2.5G, and 10G linked ports that are jumbo-frame enabled.

Up to 38 buffer memory pages are required for storing and the longest allowed jumbo frame. While there is no physical limitation to the number of ports that can be jumbo enabled, it is recommended that no more than two be enabled simultaneously to ensure system performance. There is no performance penalty for enabling additional jumbo ports beyond the potential strain on memory resources that can occur due to accumulated jumbo packets at multiple ports.

2.5 AutoDOS

The Automatic Denial-Of-Service (AutoDOS) feature detects potential DOS attacks and drops suspected incoming packets to defeat the attack. There are several possible DOS attacks that are identified based on simple classification rules that are applied to the incoming packet. Those rules, or a subset of them, must be selected for detection and dropping in unmanaged mode. Table 15 lists the DOS related classification rules that we support.

Table 15: DOS Prevention Supported in UM

DOS Type (Rule Type)	Description
MAC_LAND	MACDA=MADSA in an Ethernet packet.
IP_LAND	IPDA=IPSA in an IP (v4/v6) datagram.
TCP_BLAT	DPort=SPort in a TCP header carried in an unfragmented IP datagram or in the first fragment of a fragmented IP datagram.
UDP_BLAT	DPort=SPort in a UDP header carried in an unfragmented IP datagram or in the first fragment of a fragmented IP datagram.
TCP_NULLScan	Seq_Num=0 & All TCP_FLAGs=0, in a TCP header carried in an unfragmented IP datagram or in the first fragment of a fragmented IP datagram.
TCP_XMASScan	Seq_Num= 0 & FIN=1 & URG=1 & PSH = 1 in a TCP header carried in an unfragmented IP datagram or in the first fragment of a fragmented IP datagram.
TCP_SYNFINScan	SYN=1 & FIN=1 in a TCP header carried in an unfragmented IP datagram or in the first fragment of a fragmented IP datagram.
TCP_SYNError	SYN=1 & ACK=0 & SRC_Port<1024 in a TCP header carried in an unfragmented IP datagram or in the first fragment of a fragmented IP datagram.

Table 15: DOS Prevention Supported in UM (Continued)

DOS Type (Rule Type)	Description
TCP_FragError	The first IP fragment is not large enough to contain all required TCP header information. The total length of fragment as indicated in IP header is lesser than the combined size of IP header and TCP header.
ICMPv4_Fragment	The ICMPv4 protocol data unit carried in a fragmented IPv4 datagram.
ICMPv6_Fragment	The ICMPv6 protocol data unit carried in a fragmented IPv6 datagram.
ICMPv4_LongPing	The ICMPv4 Ping (Echo Request) protocol data unit carried in an unfragmented IPv4 datagram with its Total Length indicating a value greater than the MAX_ICMPv4_Size + size of IPv4 header.
ICMPv6_LongPing	The ICMPv6 Ping (Echo Request) protocol data unit carried in an unfragmented IPv6 datagram with its Payload Length indicating a value greater than the MAX_ICMPv6_Size.

The AutoDOS feature needs to be enabled in the configure command interface along with the set of rules that the customer would like to activate.

2.6 AutoVOIP

The Automatic Voice-Over-IP (AutoVOIP) feature detects likely VOIP streams and assigns high priority to the associated packets. The purpose is to provide better quality of service to VOIP traffic flows that are sensitive to frame delay and thus influenced by lower qualities of service. When talking on a voice-over-IP phone, a user expects to have no interruptions in the conversation and excellent voice quality. The concept is to assume that packets going to or from an IP phone vendor's equipment are likely VOIP packets, and this distinction is done based on MAC OUI field (the highest order 24 bit of the MAC Source Address). Internally, the packets with matching OUIs are assigned to traffic class (TC) of 4.

The following table lists the eight OUIs IP phone vendors which are configured for Auto VOIP by default and will be functional when AutoVOIP feature is turned on.

Table 16: Default Vendor OUIs Supported

Vendor	oui
Siemens ag phone	00:01:E3
Avaya	00:04:0D
Cisco	00:03:6B
3COM	00:E0:BB
Polycom	00:E0:75
Pingtel	00:D0:1E
H3C	00:0F:E2
NEC	00:60:B9

2.7 AutoQoS

Automatic Quality-Of-Service (AutoQOS) feature supports changing the scheduling policy at egress, enabling flow control and setting up flood limiting for broadcast, unknown unicast and multicast streams (also known as BUM traffic). Each of these features is explained in the following sections.

2.7.1 Egress Scheduling

The UM software allows users to set an egress scheduling algorithm for each queue, on each port. Scheduling can be set to either Strict Priority (SP) or Weighted Round Robin (WRR) on each port queue.

Under strict priority, a higher numbered queue is completely served before serving other lower numbered queues. In WRR, each queue is served depending on the weights specified for each queue. The WRR defaults weights are set to 1:1:2:2:4:4:8:8 weight values corresponding to queue0 to queue7. The weights for WRR can be set in range 1 to 255. Setting a weight value of zero for any queue configures strict priority for that particular queue on the specified port.

2.7.2 Flow Control

The UM software supports 802.1x PAUSE generation on enabling the AutoQoS feature. By default, Avenger responds to PAUSE frames even without enabling any AutoQoS feature. Once the AutoQoS feature is enabled, there is a separate command to enable PAUSE generation. The Avenger generates 802.1x PAUSE frames with a SMAC of 02:00:00:00:00:00.

2.7.3 Flood Limiting

The BCM53158XU UM supports a storm control/flood limit feature using forwarding meters. This provides the ability to control the rate at which broadcast, multicast, and unknown unicast packets are received. Users can set a threshold receive rate for each of the mentioned traffic type on per port basis. If the receive rate of any of the mentioned traffic type is more than the threshold set, the excess packets are dropped.

This feature is implemented in UM as SrTCM (Single rate Three Color Marking) meters defined in RFC2697 which expects users to provide Committed Information Rate (CIR) along with Committed Burst Size (CBS) and Excess Burst Size (EBS). By default, none of the meters are configured and the user must configure a profile and add it to a meter by using config commands.

UM allows users to configure 31 different profiles and assign them to a meter for a particular traffic type on a per port basis.

2.8 Auto LoopDetect

This feature is a non-spanning tree loop detect. The purpose is to provide effectively an indication (LED) of a loop, optionally disable the port, and expect that someone else will eliminate that loop (usually manually). The process is to send a Loop Detect PDU, periodically, based on a timer.

Loopdetect PDU format:

field	width	value	description
Loop_det_da	48b	0x0900090913A6	multicast destination address
Loop_det_sa	48b	MAC	system source address
Loop_det_type	16b	0x88b7	OUI extended ethertype
Protocol ID	40b	0x000AF70001	Broadcom OUI (0x000AF7), protocol # (0x0001)

field	width	value	description
Payload	24b	0x01, egress port #	Version =0x01, egress port # (2 bytes)

The source MAC address for the loopdetect PDU should be set along with config command for enabling auto loopdetect.

2.8.1 Auto Loop Detect Configurations

Each port may be enabled to send Loop Detect PDUs. The loop detect feature may be globally enabled. The loopdetect PDUs are transmitted at the interval of "5" seconds.

2.8.2 Port Shutdown Feature

The port shutdown feature will disable the port when a loop detect PDU sourced from this device returns. The feature will re-enable the port to test if the loop is still active. The desired functionality is:

- 1. Detect the port with loop.
- 2. Shut down the loop port. Set LED to show the port with loop.
- 3. After X minutes, re-enable the looped port (X is initially 2 minute).
- 4. Check for loop again.
- 5. If a loop is found, goto 2 (set X to 2X (max = 1024 mins)).
- 6. If a loop is no longer active, re-enable looped port and return port LED to normal operation (set X to 2 min).

2.9 Auto IGMP Snooping

IGMP snooping feature allows the BCM53156XU/BCM53158XU/BCM53161XU switch to listen on IGMP traffic exchanged between routers and hosts in the network. By listening, the switch learns the multicast information and program the switch hardware with multicast groups and the ports associated with them.

2.9.1 General IGMP Snooping

By default the switch floods the multicast traffic to all the ports in the broadcast domain. IGMP snooping feature tracks the multicast routers and the hosts interested in receiving the traffic for multicast groups. It uses this learned information to program the switch to forward the traffic for a specific multicast address on the interested ports rather than broadcasting to the entire domain. The maximum number of multicast groups supported is 64.Standards

The snooping implementation is based on the IETF RFC 4541. It supports the IGMPv1, IGMPv2, and IGMPv3 protocols.

- IGMPv1 (RFC 1112): Supports processing of all IGMPv1 messages. IGMPv1 does not send the explicit Leave message; the switch software removes the group membership information when the group membership interval expires.
- IGMPv2 (RFC 2236): Supports processing of all IGMPv2 messages. For the Leave messages, instead of immediately removing the group waits for the default interval expiry.
- IGMPV3 (RFC 3376): Supports the processing of IGMV3 messages, but ignores the source addresses as the switch does not support Source Specific Multicasting (SSM). If the host is interested to receive for a multicast group coming from a specific source, the switch does not support it. Instead it allows the traffic from all the sources to the host for that multicast group.

2.9.2 Static Multicast Router Interface

This feature allows static multicast router interface configuration. When an interface is configured as multicast router interface, all the IGMP report and leave messages will be sent out on the configured interface. Unlike dynamically learned multicast router interfaces, the configured ones will never expire.

2.9.3 Block Unknown Multicast Interface

This feature allows configuring the behavior of unlearned multicast traffic. If it is configured as 1 (TRUE), it drops all unlearned multicast traffic on all the ports. By default it is zero, which allows the flooding of unlearned multicast traffic.

2.9.4 Leave Implementation

Multicast groups are not removed immediately after IGMP leave messages are received. Instead waits for the configured leave time out or the max response time in the next group specific query message from the multicast routers. Implementation uses the minimum of these two values, for removing the groups. If the leave time out is configured as zero, then the multicast group is removed immediately after the IGMP leave is received.

2.10 Cascading

UM Advanced supports cascading of two BCM53158XU chips together to increase port count. The setup works as if a single high port count switch. One Avenger is primary and another is secondary based on the strap settings. The strap setting on primary is configured to a value corresponding to cascading enabled - primary and secondary device to cascading enabled - secondary. The primary Avenger is responsible for configuring both devices and is configured to boot from the M7 from flash.

These devices are connected with a SPI interface. The hardware supports memory mapping model across this interface to facilitate using the same drivers for local and remote devices. One port from each BCM53158XU is connected to facilitate packet switching across the BCM53158XU units. Customer can also configure a static LAG across any two ports (preferably 10G interfaces) in each BCM53158XU to achieve non-blocking operation.

By default, no ports are configured for cascading.

NOTE: The avenger adds 8 byte header to the frame transmitted on cascading ports.

2.11 Cable Diagnosis

UM Advanced supports Cable diag on internal GPHY ports via Enhanced Cable Diag functionality provided in phy. The cable diag feature can be initiated either through config command or through GPIO pins.

If config command is used to run the cable diags, then cable diags will run during switch init only. It can also be executed through GPIO pins on need basis. It takes approximately two seconds to run cable diags and print the results.

The config command to run the cable diags is described under section 3.2.8.

The result from Enhanced Cable Diags can be one of the following five :

- ECD busy ECD engine is busy, not able initiate cable diags
- ECD time out Cable diag initiated but not completed successfully in given time.
- Invalid Cable diag completed successfully, but result is invalid.

- Fault Cable diag completed successfully, one/more pairs have fault.
- No Fault Cable diag completed successfully, all 4 pairs are terminated properly.

In case of ECD busy result, the cable diag will stop running immediately. In case of any other result, the cable diag will continue to run on remaining ports.

The Fault result indicates that one/more pairs of the port have one of the following three faults:

- Open
- Intra short
- Inter short (cross talk)

NOTE: Any traffic flowing through the ports under cable diag will be disrupted for the duration of diagnostics, hence it is not recommended to run cable diags with traffic flowing.

2.12 Power-Saving Modes

The BCM53158XU offers different power savings modes for different operating states. All the power saving scheme are implemented without any external CPU requirement.

The various power savings modes are:

- **Auto Power Down mode:** This is a stand alone PHY feature which is enabled by a register bit setting. The PHY shuts off the analog portion of the circuitry when cable is not connected or the link partner power is down.
- Energy Efficient Ethernet (EEE) mode: Energy Efficient Ethernet is IEEE 802.1az, an extension of the IEEE 802.3 standard. IEEE defines support for the PHY to operate in Low Power Idle (LPI) mode. When enabled, this mode supports QUIET times during low link utilization, allowing the both sides of link to disable portions of each PHY's operating circuitry and save power.

NOTE: The EEE function is for the GPHY port only

2.12.1 Auto Power Down Mode

Auto Power Down mode saves PHY power consumption while the link is down. When the user enables the Auto Power Down mode through a PHY register bit setting, the PHY goes into the power savings mode automatically whenever it is in link-down state. During the Power Down state, the PHY wakes up every 2.7 or 5.4 seconds, depending on the register settings, and checks for a link signal. If no link signal is detected, then the PHY goes back to Power Down state, or the PHY wakes up and resumes the link process.

Automatic Power Down mode applies to the following conditions:

- 1. Cable is plugged in, but the link partner is shut down (for example, when a PC is off), so the port is in link down state.
- 2. Cable is unplugged, so the port is in link down state.

2.12.2 Energy Efficient Ethernet Mode

Energy Efficient Ethernet (EEE) power savings mode saves PHY power consumption while the link is up but when extended idle periods may exist between packet traffic. In EEE power savings mode PHY power consumption is scalable to the actual bandwidth utilization. The PHY can go in to "Quiet" mode (low-power idle mode) when there is no data to be transmitted. This feature is based on the latest IEEE 802.3az standard. The EEE supporting capability of the link partner is a must for this feature to work, and the discovery of the capability is during auto-negotiation through Link Layer Discovery Protocol (LLDP). This EEE feature is an embedded PHY feature and no external CPU is required.

In this mode, the MAC determines when to enter low power mode by examining the state of the transmit queues associated with each MAC. Four simple adjustments (settings) are used to trigger (optimize) the behavior of EEE control policy. These adjustments are:

- Two-part sleep delay timer
- Minimum low-power idle duration timer
- Wake transition timer

The two-way communication between the PHY and its link partner is required for the PHY to achieve the power savings on both sides. The transmit PHY sends a sleep symbol to the link partner, and the link partner enters low power state. When the transmit PHY sends a wake symbol, the regular packet transfer mode resumes.

Chapter 3: Applications and Configuration

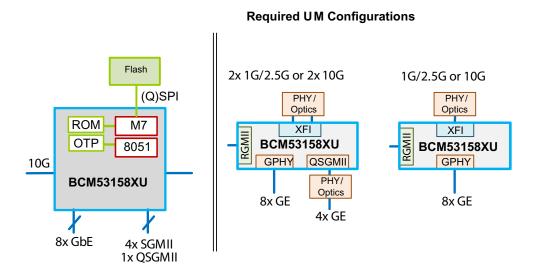
3.1 Overview

The BCM53158XU supports unmanaged, web managed, and fully managed modes of operation. Each of these modes is discussed in more detail in the following sections.

3.2 Unmanaged Applications (UM)

UM operation is an out-of-box operation. When power is applied to the box, it will initialize and forward frames without any other configuration or external interaction. This configuration uses the integrated M7 CPU. The device automatically forwards frames after power is applied. The configuration of the system is static and completely contained within the Flash. Figure 4 provides an overview of the SKUs supported.

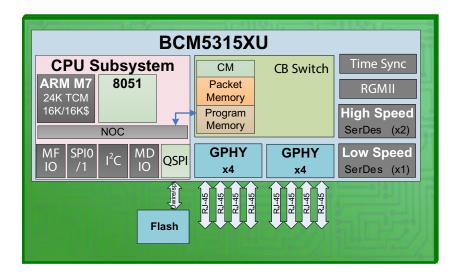
Figure 4: Unmanaged Applications



3.2.1 Unmanaged Base Configuration

The basic unmanaged configuration is the simplest possible application for BCM53158XU. In this case, only the internal PHY are used (8x1G). Figure 5 depicts the unmanaged base configuration.

Figure 5: Basic Unmanaged Configuration



The operational processors are the internal 8051 and integrated M7 CPU. The 8051 recognizes OTP and activates the M7. AVS and the rest of the Unmanaged software is running on the M7. An external Flash is required for AVS and is also used for optional customer configuration or bug fixes. Table 17 shows the valid straps and OTP in this configuration.

Table 17: Basic Unmanaged OTP and Strap Configuration

OTP Feature	Values	Strap Feature	Values
XFI Disable	Enabled (off)	M7_Boot_src	M7 Flash
QSMII Disabled	Enabled (off)	Enable_qspi	Disable
ARL SIZE	8K Entries	Cascading_config	Stand-alone, hardware forwarding.
LIM Disable	Enabled (off)	-	_
CFP Disable	Enabled (off)	-	_
Robo 2 switch Buffer Size ^a	512-8K PB, 8 KB 8051	-	-
RGMII Disable	Disabled (on)	-	-
GPHY Disable	Disabled (on)	-	_
1G Disable	Disabled (on)	-	_

a. All SKUs for UM mode are restricted by the OTP to only 128 KB of the 1 MB of memory.

The embedded 8051 is responsible for the following features in this mode:

- Processing of straps and OTP configurations (ROM CODE)
- 8051 enters sleep mode and periodically runs link scan and error code (ROM CODE)

The integrated M7 CPU is responsible for the following features in this mode:

- AVS mechanism running (M7 Flash code)
- Basic unmanaged configuration of the switch core (M7 Flash code)
- Enabling internal PHYs (M7 Flash code)
- Enable forwarding (ROM CODE)
- Periodically runs link scan and error code (M7 Flash code)

3.2.2 Unmanaged with Advanced Features

The unmanaged applications have four value added features: AutoVOIP, AutoDOS, AutoQoS, and AutoLoopDetect. These four features require an external SPI Flash to hold the configuration and program data for the integrated M7 CPU. The following is a list of functions performed:

- Processing of straps and OTP configurations (ROM CODE)
- AVS mechanism running (M7 Flash code)
- Basic unmanaged configuration of the switch core (M7 Flash code)
- Enabling AutoVOIP, AutoDOS, and AutoQoS configuration (M7 Flash code)
- Enabling internal PHYs (M7 Flash Code)
- Enable forwarding (M7 Flash Code)
- Vectoring (executing from Flash) to AutoLoopDetect Application Code or enters sleep mode (M7 Flash code)
- Periodically runs link scan and error code (ROM CODE)

3.2.3 High-Speed Unmanaged

The internal SerDes or external devices (PHY, PSE, etc.) require additional code space and complexity. Figure 6 on page 45 provides a sample configuration of this application with external PSE, 10G, and 1G copper PHYs.

Figure 6: High-Speed Unmanaged

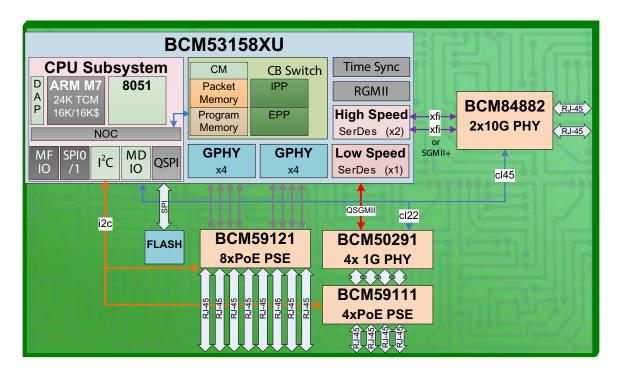


Table 18 describes the values for the valid OTP and strap settings.

Table 18: High-Speed Unmanaged OTP and Strap Configuration

OTP Feature	Values	Strap Feature	Values
XFI Disable	Disabled (on)	M7_Boot_src	M7 Flash

Table 18: High-Speed Unmanaged OTP and Strap Configuration (Continued)

OTP Feature	Values	Strap Feature	Values		
QSMII Disabled	Disabled (on)	Enable_qspi	Disable		
ARL SIZE	16K Entries	Cascading_config	Stand-alone, hardware forwarding.		
LIM Disable	Enabled (off)	_	_		
CFP Disable	Enabled (off)	_	-		
Robo 2 switch Buffer Size ^a	1 MB-8K PB, 8 KB 8051	-	-		
RGMII Disable	Disabled (on)	_	_		
GPHY Disable	Disabled (on)	_	-		
1G Disable	Disabled (on)	-	-		

a. All SKUs for UM mode are restricted by the OTP to only 128 KB of the 1 MB of memory.

In this mode, the advanced 'auto' features are also available. The M7 Flash code in this case implements the following features:

- Processing of straps and OTP configurations (ROM CODE)
- Basic unmanaged configuration of the switch core (M7 Flash CODE)
- Configuration of the internal SerDes (M7 Flash Code)
- Configuration of external PHYs, PSE, etc. (M7 Flash Code)
- Enabling AutoVOIP, AutoDoS, AutoQoS, AutoLoopDetect configuration (M7 Flash Code)
- Play out customer specific configuration from to both internal and external devices (I²C, MDIO) (M7 Flash Code)
- Enabling internal PHYs (M7 Flash Code)
- Enable forwarding (M7 Flash Code)
- Vectoring (executing from Flash XIP) to AutoLoopDetect Application Code or enters sleep mode (M7 Flash Code)
- Periodically runs link scan and error code (ROM CODE)

3.2.4 Unmanaged Cascade Support

In this application, two BCM53158XU are connected together to provide more ports to the system. There are two different configurations shown. Figure 7 shows the first, which is a blocking configuration that provides 24x1G port with 2x10G external ports.

Figure 7: Unmanaged Cascade 24+2 Blocking

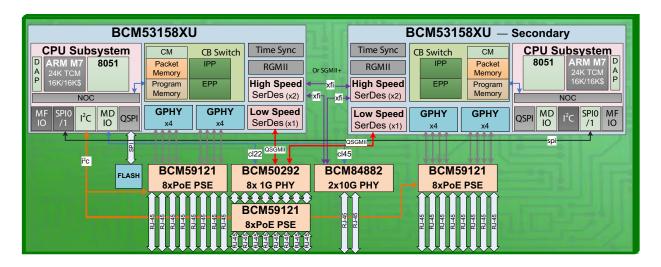


Figure 8 on page 47 has a similar configuration, except a LAG is used across the 10G interface between two BCM53158XU to achieve non-blocking operation.

Figure 8: Unmanaged Nonblocking 24G Solution

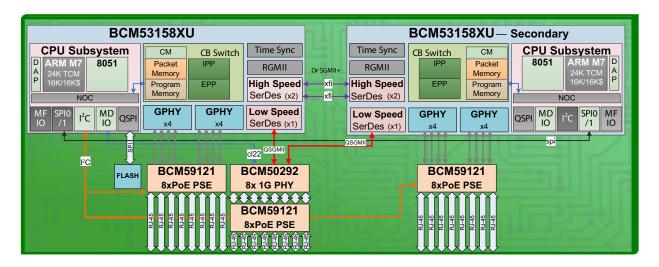


Table 19 describes the values for the valid OTP and strap settings.

Table 19: High-Speed Unmanaged OTP and Strap Configuration

OTP Feature	Values	Strap Feature	Values
XFI Disable	Disabled (on)	Boot_src	M7 Flash
QSMII Disabled	Disabled (on)	Enable_qspi	Disable
ARL SIZE	16K Entries	Cascading_config	Primary vs Secondary
LIM Disable	Enabled (off)	_	_
CFP Disable	Enabled (off)	_	_

Table 19: High-Speed Unmanaged OTP and Strap Configuration (Continued)

OTP Feature	Values	Strap Feature	Values
Robo 2 switch Buffer Size ^a	1 MB-8K PB, 8 KB 8051	_	_
RGMII Disable	Disabled (on)	_	_
GPHY Disable	Disabled (on)	_	_
1G Disable	Disabled (on)	_	_

a. All SKUs for UM mode are restricted by the OTP to only 128 KB of the 1 MB of memory.

In this mode, the advanced 'auto' features are also available. In this system, there are two BCM53158XU where one is the primary and one is the secondary based on a strapping. The primary BCM53158XU is responsible for configuring both devices. These devices are connected with an SPI interface. The hardware supports memory mapping model across this interface to facilitate using the same drivers for local and remote devices. External devices, such as PHYS and PSE are connected to the Primary BCM53158XU.

The M7 Flash code on the primary BCM53158XU implements the following features:

- Processing of straps and OTP configurations (ROM CODE)
- Basic unmanaged configuration of the switch core (M7 Flash code)
- Configuration of the SerDes on Primary (M7 Flash code)
- Configuration of cascade on Primary (M7 Flash code)
- Configuration of the SerDes on Secondary (M7 Flash code)
- Configuration of cascade on Secondary (M7 Flash code)
- Configuration of external PHYs, PSE, and so forth (M7 Flash code)
- Enabling AutoVOIP, AutoDoS, and AutoQoS configuration (M7 Flash code)
- Play out customer specific configuration from Flash to both internal and external devices (I²C, MDIO) (M7 Flash code)
- Enable internal PHYs on Primary (M7 Flash code)
- Enable internal PHYs on Secondary this is via the MDIO on in the secondary device (M7 Flash code)
- Enable external PHYs (M7 Flash code)
- Enable forwarding on both Primary and Secondary devices (M7 Flash code)
- Vectoring (executing from flash) to AutoLoopDetect Application Code or enters sleep mode (M7 Flash code)

The M7 on the secondary BCM53158XU device implements the following features:

- Processing of straps and OTP configurations (ROM CODE)
- Basic unmanaged configuration of the switch core (M7 Flash code)
- Identified as secondary based on straps (M7 Flash code)
- Does NOT enable PHYS or unmanaged forwarding (M7 Flash code)

Chapter 4: Software Components

This section describes on of the software components the will run on the BCM53158XU. This is not an exhaustive list.

4.1 8051 and M7 Running Environment

The operating environment is a bare metal environment. The following is list of components in the ROM environment:

Running on the 8051:

SKU/OTP/Strap processing (ROM) – Process straps, OTP and SKUS options.

Running on the M7:

- AVS mechanism
- Based device setup (ROM) Configures PLL, clocks, and central memory.
- Basic Unmanaged Configuration (ROM) Configures the Robo 2 switch core for default unmanaged configuration.
- Internal GPHY configuration (ROM) Configures and enables GPHY ports.
- Link scan/error handling (ROM) handles links going up and down as well and any errors (ECC).

The following are advanced unmanaged features:

- Advanced registered playback Reads register play-back data from the QSPI Flash and applies it to the device and external components via MDIO and I²C.
- AutoVOIP/AutoQoS/AutoDOS Configures these features (that is, OUI and voice VLAN) from flash.
- AutoLoopDetect Operation code which performs autoloopdetect feature. This runs from flash.

4.2 M7 Operating System Environment

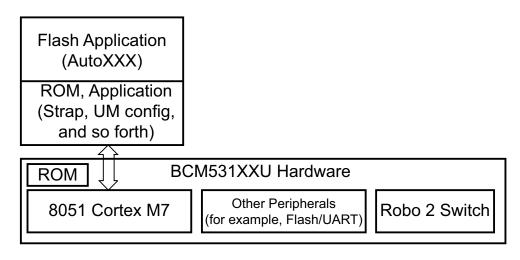
The M7 uses an operating system environment based on OpenRTOS/FreeRTOS. The following is a list of features:

■ ARM CMSIS-Driver (ARM) – Portable device driver infrastructure.

4.3 Unmanaged Application

Figure 9 shows the basic unmanaged software components.

Figure 9: Unmanaged Software Components



Chapter 5: System Interfaces

5.1 Overview

The BCM53158XU include the following interfaces:

- Copper Interface
- Frame Management Port Interface
- SerDes Interface
- Configuration Pins
- Programming Interfaces
- LED Interfaces
- Digital Voltage Regulator (LDO)

Each interface is discussed in detail in these sections.

5.2 Copper Interface

The internal PHYs transmit and receive data using the analog copper interface. This section discusses the following topics:

- Auto-Negotiation
- Lineside (Remote) Loopback Mode

5.2.1 Auto-Negotiation

The BCM53158XU negotiate a mode of operation over the copper media using the auto-negotiation mechanism defined in the IEEE 802.3u and IEEE 802.3ab specifications. When the auto-negotiation function is enabled, the BCM53158XU automatically choose the mode of operation by advertising its abilities and comparing them with those received from its link partner. The BCM53158XU can be configured to advertise the following modes:

- 1000BASE-T full-duplex and/or half-duplex.
- 100BASE-TX full-duplex and/or half-duplex.
- 10BASE-T full-duplex and/or half-duplex.

The transceiver negotiates with its link partner and chooses the highest common operating speed and duplex mode, commonly referred to as highest common denominator (HCD). Auto-negotiation can be disabled by software control, but is required for 1000BASE-T operation.

5.2.2 Lineside (Remote) Loopback Mode

The lineside loopback mode allows the testing of the copper interface from the link partner. This mode is enabled by setting bit 15 of the Miscellaneous Test register. The MDI receive packet is passed through the PCS and sent back out as the MDI transmit packet. The PCS receive data appears on the internal MAC interface.

5.3 Frame Management Port Interface

The dedicated frame management port provides high-speed connection to transfer management packets to an external management agent. For more information about frame management, see "Interdevice Interface" on page 24. The port is configurable to RGMII using strap pins or software configuration.

NOTE: The Frame Management port interface supports only full-duplex mode.

The BCM53158XU supports EEE features for external PHYs connected on the IMP and GMII (port5) only through the GMII interface.

5.3.1 RGMII Interface

The Reduced Gigabit Media Independent Interface (RGMII) serves as a digital data interface between the BCM53158XU and an external management entity or an external PHY to provide additional data port capacity. Transmit and receive data is clocked on the rising and falling edge of the clocks. This reduces the number of data signals crossing the MAC interface without affecting the data transmission rate. The RGMII transmits data synchronously using the TXD[3:0] and RXD[3:0] data signals. The BCM53158XU offers either 2.5V or 1.5V RGMII interface with an external device.

5.4 SerDes Interface

The BCM53158XU provides 1x QSGMII (BCM53158 Only) + 2x XFI interfaces.

5.5 Configuration Pins

Initial configuration of the BCM53158XU takes place during power-on/reset by loading internal control values from hardware strap pins. The value of the pin is loaded when the reset sequence completes, and the pin transitions to normal operation. Pull-up or pull-down resistors can be added to these pins to control the device configuration. If the pins are left floating, the default value is determined based on the internal pull-up or pull-down configuration. See "Signal Descriptions" on page 69 for additional information.

5.6 Programming Interfaces

The BCM53158XU can be programmed using the SPI interface. The interfaces share a common pin set that is configured using the strap pin. The "SPI Interface" provides access for a general-purpose microcontroller, allowing read and write access to the internal BCM53158XU register space. It is configured to be compatible with the Motorola Serial Peripheral Interface (SPI) protocol.

An explanation follows for using the serial interface with an SPI-compatible CPU ("SPI Interface"). Either mode can be selected with the strap pin. Either mode has access to the same register space.

5.6.1 SPI Interface

One way to access the BCM53158XU internal registers is to use the SPI-compatible interface. This four-pin interface is designed to support a fully functional, bidirectional Motorola serial peripheral interface (SPI) for register read/write access. In addition, there is another SPI master for cascading configuration. The maximum speed of operation is 25 MHz.

5.6.2 SPI Slave

The SPI2 is a four-pin interface that comprises the following:

- SS2 Slave select is used to signal start, end of transaction by the master.
- SCK2 Slave Clock driven by Master.

- MOSI2 Master output/slave input is used to send command, address and write data from the master. Data is received by slave one bit per clock; the endian-ness is Big endian.
- MISO2 Master input/slave output is used to send read data from Slave. Data is sending one bit per clock, the endianness is Big endian.

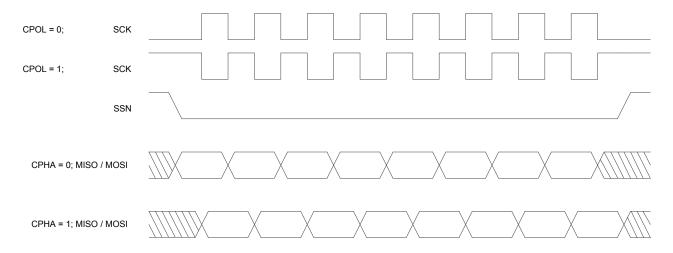
NOTE: In the BCM53158XU, the maximum SPI slave SCK frequency can be 25 MHz when the internal clock is 400 MHz and 20 MHz when internal the clock is 200 MHz.

5.6.2.1 SPI Transactions

In the idle state, the SSN should remain high and the SCK should be low. The master driving the SSN low indicates the start of the transaction. The SSN is held low until the end of the transaction. The clock is given by the master only when the SSN is low. The MOSI is used by the master to send the command, read the address, write the address, and write Data. The MISO is used to send back read data and status from the slave.

5.6.2.1.1 Clock Polarity and Phase

Figure 10: CPOL and CPHA



The CPOL are used to specify the base value of SCK, such as, value of SCK when in an idle state. The CPHA specifies the edges at which the data needs to be launched and captured. CPHA = 0 means transmitting data on the active to an idle state transition of SCK and capturing it on idle to active state transition. CPHA = 1 means transmitting data on the idle to active state transition of SCK and capturing it on active to idle state transition.

The SPI slave in the BCM53158XU supports mode 1 (CPOL = 0/CPHA = 1) only on the A1 version. No other combination is supported. The SCK is low when idle. Transmit data is on the positive edge and receive is on the negative edge of SCK.

The SPI slave in the BCM53158XU supports mode 1 (CPOL = 0/CPHA = 1) and mode 3 (CPOL = 1/CPHA = 1) on the B0 version. The default configuration is mode 3 support and can change to mode 1 support through a software override.

5.6.2.1.2 Fields

The following fields are used by SPI in BCM53158XU.

Table 20: Fields used in SPI

Field	No. of Bits	Description
Command	8	The command word specifies the operation to be performed.
Address	32	Address to be read/written to, given by SPI Master.
Status	16	Status of the latest Reads/Writes from SPIS. Separate status bytes are kept for reads and writes. And for overall SPI status.
Ack/Nack	8	Used only in Fast mode, to convey status of read, from SPIS.
Write Data	32x	Write Data is of variable length, but always in chunks of 32 bits as specified in the command word by the Master.
Read Data	32x	Read data will be of variable length, but always read in chunks of 32 bits from SPIS.

5.6.2.1.3 Command Word Format

Every transaction starts with the SSN going low. The first field after the SSN going low is the command. Multiple command word fields cannot exist in the same transaction. An 8-bit command word is used in the SPIS. The organization of the command word is as shown in Table 21 on page 54.

Table 21: Command Word Format

7	6	5	4	3	2	1	0
Transaction (Txn[3:0])				blen[2:0]			unused

To avoid confusion, read and write are termed as operations, while a transaction starts with SSN (active) going low and ends when the SSN goes high. A read or write operation may contain one or more transactions. The first field (in this case byte) is the command word.

5.6.2.1.4 Burst Length

Burst length is specified by the "blen" field in the command word for both read and write. Burst length is defined as follows:

Burst_length = blen[2:0]+1.

One burst equals 4 bytes. Write/read data needs to always be in multiples of 4 bytes.

5.6.2.1.5 Supported Transactions

The SPI slave supports the following transactions, encoded using txn[3:0] as shown in Table 22.

Table 22: Transactions

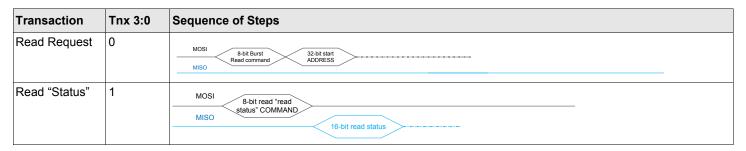


Table 22: Transactions (Continued)

Transaction	Tnx 3:0	Sequence of Steps
Read "Read Data"	2	MOSI 8-bit read data COMMAND 32-bit read data 32-bit read data
Write Request	4	MOSI 8-bit Burst 32-bit start ADDRESS N=Burst size N=Burst size N=Burst size N=Burst size N x 32-bit write data ADDRESS N x 32-bit write data
Read "Write Status"	5	MOSI 8-bit read write- status COMMAND 16-bit write status
Fastmode Read	6	MOSI B-bit fast read COMMAND ADDRESS B-bit NACK Status B-bit ACK STATUS 32-bit read data
Fastmode Write	7	MOSI S-bit fast Write COMMAND ADDRESS 32-bit write data ADDRESS 8-bit NACK Status 8-bit ACK STATUS
Read SPI Status	8	MOSI 8-bit read read-status COMMAND 16-bit read status
Clear SPI Status	9	MOSI 8-bit SPIS status clear COMMAND 8'h00
Reset SPIS	10	MOSI 8-bit SPIS reset COMMAND 8'h00
Reset Chip	11	MOSI 8-bit CHIP reset COMMAND 8'h00

The total outstanding for both read and write is eight. The burst size limit is eight. In case the SPI slave receives more than eight requests for either a read or write, all requests after the limit (eight) is reached are aborted and an error status is reported through the SPI status register.

5.6.2.1.6 SPIS and Chip Reset

Two following reset transactions are provided in SPI Slave:

- SPIS Reset Used to reset the SPI slave. This does not look at the state of the module before resetting it.
- Chip Reset Tis generates a chip reset request, which goes to the CRU.

5.6.2.1.7 Read/Write Status Format

Read/Write status registers are 16-bit registers implemented as 2-bits per outstanding. The maximum number of outstanding transfers in which the slave can report status is eight. This 2-bit status reported by slave is encoded as follows:

- 2'b00 Idle
- 2'b01 Incomplete/Transaction Ongoing
- 2'b10 Transaction finished successfully.
- 2'b11 Transaction finished with error.

This only indicates the transaction status. In case of an error, the master can read the SPI status register to find the cause.

Table 23: Read/Write Status Register Format

15:14	13:12	11:10	9:8	7:6	5:4	3:2	1:0
Status _N	Status _{N-1}	Status _{N-2}	Status _{N-3}	Status _{N-4}	Status _{N-5}	Status _{N-6}	Status _{N-7}

5.6.2.1.8 SPI Status

SPI status will be implemented as a 16-bit status register as shown in Table 24.

Table 24: SPI Status Register Format

Bits	Field	Description
0	wr_ovf	Indicates that write requests overflowed. BCM5315X/BCM5316X supports up to 8 outstanding requests. Outstanding in this context of write means the status of write had not been read.
1	wr_abort	Indicates a write transaction on SPI had been terminated before it is complete.
2	wr_fm_oveflow	Fast mode write request received when there are outstanding write transactions. Fast mode should only be use when there are no outstanding transactions.
3	wr_fm_abort	Fast mode transaction aborted by SPI master
4	wr_axi_slverr	Slave error from NIC. Used when the access has reached the slave successfully, but the slave wishes to return an error condition to the originating master.
5	wr_axi_decerr	Decode error from NIC. Generated, typically by an interconnect component, to indicate that there is no slave at the transaction address.
6	_	Unused
7	_	Unused
8	rd_ovf	Indicates that read requests overflowed. BCM5315X/BCM5316X supports up to 8 outstanding requests. Outstanding in this context of read means that the data had not been read.
9	rd_abort	Indicates a read request transaction on SPI had been terminated during the address phase.
10	rd_fm_oveflow	Fast mode read request received when there are outstanding write transactions. Fast mode should only be used when there are no outstanding transactions.
11	rd_fm_abort	Fast mode read transaction aborted by External master
12	rd_axi_slverr	Slave error from NIC. Used when the access has reached the slave successfully, but the slave wishes to return an error condition to the originating master
13	rd_axi_decerr	Decode error from NIC. Generated, typically by an interconnect component, to indicate that there is no slave at the transaction address.
14	_	Unused
15	_	Unused

5.6.2.1.9 ACK/NACK Byte Format

ACK/NACK bytes are used to convey the status of fast mode read and write transactions.

Table 25: ACK/NACK Byte Format

7	6	5	4	3	2	1	0
Unused (0)	•	•		•		txn_error	txn_done

The txn_error field is used to indicate that an error has occurred in the fast mode transaction. It is valid only if a transaction is done, that is, txn_done = 1;

5.6.2.2 SPI Slave Operation

The BCM53158XU supports the following SPI slave operations:

5.6.2.2.1 Slave Mode Normal Write

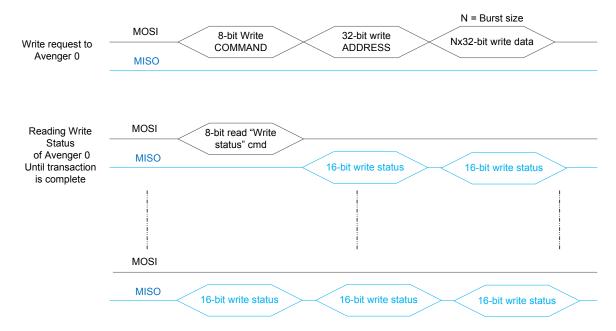
In a Normal Write operation, an 8-bit command, which specifies the operation to be performed and the size of write data in chunks of 32-bit words, is followed by 32-bit write address and write data.

Out of reset, all eight status fields in status a register are in an IDLE status. When a write request is received, the corresponding status field is updated to an INCOMPLETE status. When the write is done or if an error is reported, the status is updated to a FINISHED SUCCESSFULLY or a FINISHED WITH ERROR status, respectively. This status is retained until the Master reads this status, after which it is cleared to IDLE status.

The status is implemented like a shift register. Every new request would result in the status being left-shifted by two (with INCOMPLETE status). A burst of length N, is treated like N separate writes, and hence, results in the status being right-shifted by N*2(with INCOMPLETE status). In case the burst write request results in the number of outstanding transactions crossing the limit of eight, the whole write request is discarded and the write status is not updated, such as, it remains IDLE. Only the SPI status register flags the error status.

A write operation is considered finished only after the write done status is conveyed to the master. Until the status is given to the master, the status is retained in the write status register.

Figure 11: Slave Mode Normal Write



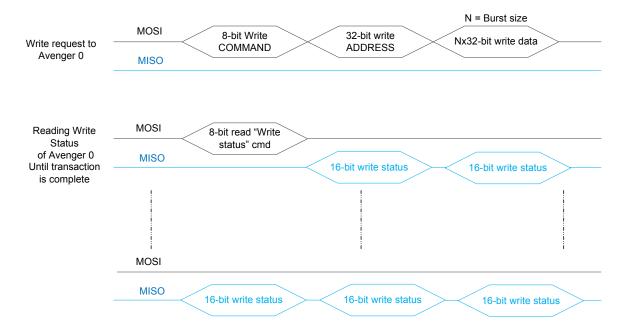
5.6.2.2.2 Slave Mode Normal Read

Out of reset, all eight status fields in the read status register are in an IDLE status. When a read request is received, the corresponding status field is updated to an INCOMPLETE status. When the read data is ready or if an error is reported, the status is updated to a FINISHED SUCCESSFULLY or a FINISHED WITH ERROR status respectively. This status is retained until the Master reads this status, after which it is cleared to IDLE status.

The status is implemented like a shift register. Every new request results in the status being left-shifted by two (with INCOMPLETE status). A burst of length N, is treated like N separate reads, and hence, results in the status being right-shifted by N*2(with INCOMPLETE status). In case the a burst read request results in the number of outstanding transactions crossing the limit of eight, the whole read request is discarded. The read status is not updated, that is, it remains IDLE. Only the SPI status register flags the error status.

In this case, the status of the transaction is incomplete in the status field, but the data is read, and the read data given out, is incorrect. A read operation is considered finished only after the read done status is conveyed to the master and master has read the data. Until the read data is given to the master, the status is retained in the read status register.

Figure 12: Slave Mode Normal Read



5.6.2.2.3 Slave Mode Fast Read

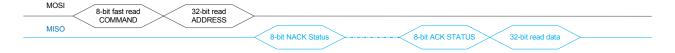
Fast mode (FM) read finishes in a single transaction. After the address field is sent the slave starts send NACK bytes, until the data is ready. Once the ready, it sends an ACK followed by 32-bit read data.

Fast mode does not support burst. It should not be done when there are outstanding transactions. If a fast read transaction is terminated in the middle of a transfer, the read data is lost.

This is the fastest way SPI can be used for a single read.

If a fast mode read is abandoned, the status and data are forever lost. An error is reported only using SPI status register.

Figure 13: Slave Mode Fast Read



5.6.2.2.4 Slave Mode Fast Write

FM write finishes in a single transaction. After the address and 32-bit data fields are sent, the slave starts to send NACK bytes until the data is ready. Once ready, it sends ACK bytes.

Fast mode does not support burst. It should not be done when there are outstanding transactions. If a fast write transaction is terminated in the middle of a transfer, the action depends on the field being sent. If the write data is not fully received, the transaction is aborted unless the write data is received at SPI slave. The transaction happens but the status is lost.

This is the fastest way an SPI can be used for a single write.

If a fast-mode write transaction is aborted, the status is lost. The write may or may not happen on NIC based on the stage at which the transaction was aborted.

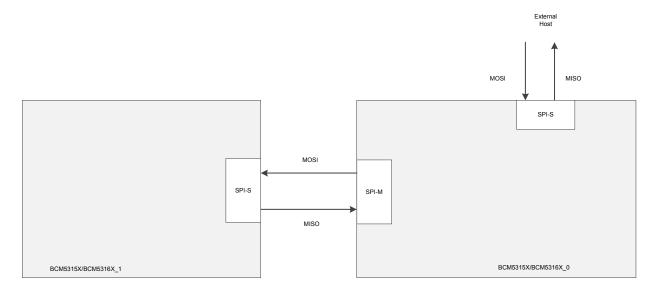
Figure 14: Slave Mode Fast Write



5.6.3 SPI Master

In cascaded mode, BCM53158XU_0 and BCM53158XU_1 are connected together using an SPI interface. SPI1 is an SPI Master-only interface; SPI2 is an SPI Slave-only interface. Figure 15 illustrates this scenario.

Figure 15: Block Diagram of SPI Connection for Cascading



5.6.3.1 SPI Master Operation

The BCM53158XU supports the following SPI master operations:

5.6.3.1.1 Master Mode Normal Write

In a Normal Write operation, an 8-bit command, which specifies the operation to be performed and the size of write data in chunks of 32-bit words, is followed by 32-bit write address and write data.

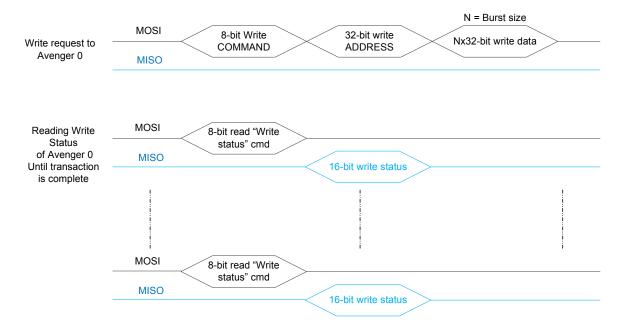
After the write data is sent, the master may choose to start sending another set of address/data in the same transaction.

Out of reset, all eight status fields in the status register are in an IDLE status. When a write request is received, the corresponding status field is updated to an INCOMPLETE status. When the write is done or if an error is reported, the status is updated to a FINISHED SUCCESSFULLY or a FINISHED WITH ERROR status, respectively. This status is retained until the Master reads this status, after which it is cleared to an IDLE status.

The status is implemented like a shift register. Every new request results in the status being left shifted by two (with INCOMPLETE status). A burst of length N, is treated like N separate writes, and hence, results in status being right shifted by N*2(with INCOMPLETE status). In case the a burst write request result in the number of outstanding transactions crossing the limit of eight, the whole write request is discarded. The write status is not updated, that is, it remains IDLE. Only the SPI status register flags the error status.

A write operation is considered finished only after the write done status is conveyed to the master. Until the status is given to the master, the status is retained in the write status register.

Figure 16: Master Mode Normal Write



5.6.3.1.2 Master Mode Normal Read

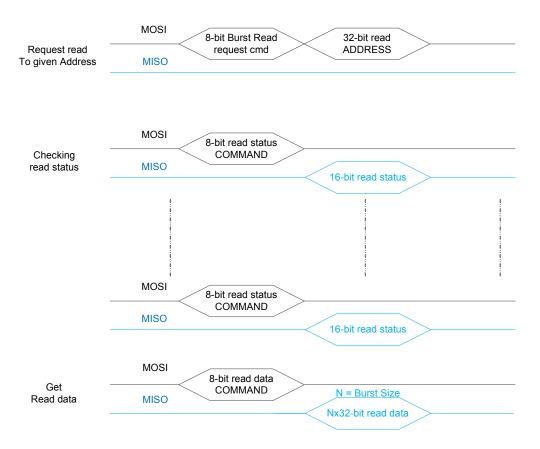
Out of reset, all eight status fields in the read status register are in an IDLE status. When a read request is received, the corresponding status field is updated to an INCOMPLETE status. When the read data is ready or if an error is reported, the status is updated to a FINISHED SUCCESSFULLY or a FINISHED WITH ERROR status respectively. This status is retained until the Master reads this status, after which it is cleared to an IDLE status.

The status is implemented like a shift register. Every new request results in the status being left shifted by two (with INCOMPLETE status). A burst of length N is treated like N separate reads, and hence, results in the status being right shifted by N*2(with INCOMPLETE status). In case the a burst read request would result in the number of outstanding transactions crossing the limit of eight, the whole read request is discarded. The read status is not updated, that is, it remains IDLE. Only the SPI status register flags the error status.

In case the status of the transaction is incomplete in the status field but the data is read, the read data given out is incorrect. A read operation is considered finished only after the read done status is conveyed to the master and the master has read the data. Until the read data is given to the master, the status is retained in the read status register.

If the SPI Master has the capability to detect the read status live (without delay), it can choose to continue with the read status transaction and poll for the status, or if it is known that the status is ready, the master can use the read "read status + data" transaction, which can send data in the same transaction.

Figure 17: Master Mode Normal Read



5.6.4 Quad SPI Flash Interface

The BCM53158XU offers a quad SPI interface and supports Execute in Place (XIP) as a boot source configured by a strapped option. The interface comprises six signal pins: chip select (SS), Flash clock (SCK), Data input/output (DATA0~3).

NOTE: EPROM and QSPI are both muxed in the same pins, therefore these two interfaces are exclusive.

5.6.5 MDC/MDIO Interface

The BCM53158XU offers an MDC/MDIO interface (support both CL22 and CL45) for accessing the PHY registers. The PHY registers are accessed directly by using direct PHY addresses from 0x01~0x08.

5.6.5.1 MDC/MDIO Interface Register Programming

The BCM53158XU are designed to be fully compliant with the MII clause of the IEEE 802.3u Ethernet specification. The MDC pin of the BCM53158XU sources a 2.5 MHz clock. Serial bidirectional data transmitted using the MDIO pin is synchronized with the MDC clock. Each MII read or write instruction is initiated by the BCM53158XU and contains the following:

- **Preamble (PRE)** To signal the beginning of an MII instruction after reset, at least 32 consecutive 1-bits must be written to the MDIO pin. A preamble of 32 1-bits is required only for the first read or write following reset. A preamble of fewer than 32 1-bits causes the remainder of the instruction to be ignored.
- Start of Frame (ST) A 01 pattern indicates that the start of the instruction follows.
- Operation Code (OP) A read instruction is indicated by 10, while a write instruction is indicated by 01.
- PHY Address (PHYAD) A 5-bit PHY address follows, with the MSB transmitted first. The PHY address allows a single MDIO bus to access multiple PHY chips.
- Register Address (REGAD) A 5-bit register address follows, with the MSB transmitted first.
- Turnaround (TA) The next bit times are used to avoid contention on the MDIO pin when a read operation is performed. When a write operation is being performed, 10 must be sent by the BCM53158XU chip during these two bit times. When a read operation is being performed, the MDIO pin of the BCM53158XU must be put in a high-impedance state during these bit times. The external PHY drives the MDIO pin to 0 during the second bit time.
- **Data** The last 16 bits of the Instruction are the actual data bits. During a write operation, these bits are written to the MDIO pin with the most significant bit (MSB) transmitted first by the BCM53158XU. During a read operation, the data bits are driven by the external PHY with the MSB transmitted first.

Table 26 summarizes the complete management frame format.

Table 26: MII Management Frame Format

Operation	PRE	ST	ОР	PHYAD	REGAD	TA	Data	Direction
Read	1 1	01	10	AAAAA	RRRRR	ZZ Z0	D D	Driven by master Driven by slave
Write	1 1	01	01	AAAAA	RRRRR	10	D D	Driven to master

Table 27: PHY MDIO Address Map

MDIO Slave	MDIO Address
GPHY0-0	1
GPHY0-1	2

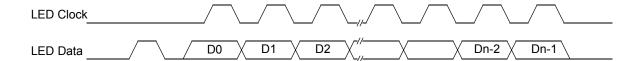
Table 27: PHY MDIO Address Map (Continued)

MDIO Slave	MDIO Address
GPHY0-2	3
GPHY0-3	4
GPHY1-0	5
GPHY1-1	6
GPHY1-2	7
GPHY1-3	8
EAGLE PHY 0	9
EAGLE PHY 1	10
QSGMII/Combo PHY	11
Reserved for QSGMII	12-14

5.7 LED Interfaces

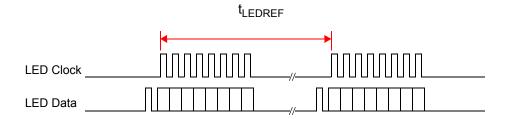
The CMICd provides two LED processors capable of retrieving status information from the ports in the device. After the status information has been retrieved and stored in the LED processor's memory, a user-created program is run that allows the LED process to build a serial bit-stream based on the LED status information. The BCM53158XU splits the task of LED managements across the two LED processors, such that LED processor 0 is responsible for all of the Warpcore[®]-based and UNICORE-based ports, and LED processor 1 is responsible for the two Ethernet interfaces in the iProc and the Gigabit SerDes port. Each LED processor has a two-wire (clock and data) interface to control system LEDs. Both signals are held low during periods of inactivity. A single LED refresh cycle consists of clocking out a programmable number of LED data bits. The LED data signal is pulsed high at the start of each LED refresh cycle (see Figure 18).

Figure 18: Single LED Refresh Cycle



The LED refresh cycle is repeated periodically to refresh the LEDs (see Figure 19 on page 64).

Figure 19: LED Refresh Timing



5.8 Digital Voltage Regulator (LDO)

The BCM53158XU LDO generates a 1.8V power supply. The 1.8V is used internally as an intermediate voltage level in 28 nm technology.

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5.9 MFIO Interface

The BCM53158XU offers a total of nine MFIO pins. Those MFIO pins can be programmable to operate in different function modes,

Table 28 lists the modes of each MFIO pin.

Table 28 lists the modes of each MFIO pin.

Table 28: MFIO Interface Pins

Pins	Debug Mode	Direction	Notes	GPIO Mode	Direction	Notes	XFP Management Mode	Direction
MFIO_0	uart_rxd	Input		GPIO_0	Inout	-	GPIO_0	Inout
MFIO_1	uart_txd	Output	-	GPIO_1	Inout	_	clkout	Output
			Power on default					
MFIO_2	clkout	Output	(clkout can be any	GPIO_2	Inout	_	XFP0_Mod_ABS	Input
MFIO_3	pwm0	Output	selected internal clock, for debug and test.)	GPIO_3	Inout	-	XFP0_intr_n	Input
MFIO_4	Reset_out	Output		GPIO_4	Inout	-	XFP0_TX_DIS	Output
MFIO_5	pwm1	Output		GPIO_5	Inout	_	XFP0_Mod_DeSel	Output
MFIO_6	pwm2	Output		GPIO_6	Inout	_	XFP0_RX_LOS	Input
MFIO_7	pwm3	Output	=	GPIO_7	Inout	_	XFP0_RST	Output
MFIO_8	FRAME_SY	Inout	=	GPIO_8	Inout	_	XFP0_Mod_NR	Input

NOTE:

- 1. Each MFIO function can be selected independently using respective sel_mfio*.
- 2. The function of words in bold can be muxed to different functions for coexisting UART/I²C and both XFIs control signa (AVR-ER 04 and AVR-ER 05) through register CRU_CRU_MFIO_control_register_2 bit 31: MFIO_COMPATIBILITY

Table 29: MFIO Muxing Function in the B0 Chip for the 13x13 mm² Package

Mode	MFIO_COMPATIBILITY_MODE	XFP Mode	
MFIO	Address: 0x40200374 Bit 31	MFIO_5	MFIO_7

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Table 29: MFIO Muxing Function in the B0 Chip for the 13x13 mm² Package (Continued)

Mode	MFIO_COMPATIBILITY_MODE	XFP Mode	
A0/A1	0	XFP0_Mod_DeSel	XFP0_RST
В0	1	XFP1_intr_n	XFP1_RX_LOS

Chapter 6: Hardware Signal Definitions

6.1 I/O Signal Types

Table 30 shows the conventions that are used to identify the I/O types. The I/O pin type is useful in referencing the DC pin characteristics.

Table 30: I/O Signal Type Definitions

Abbreviation	Description
XYZ	Active-low signal
3T	3.3V tolerant
Α	Analog pin type
В	Bias pin type
CS	Continuously sampled
D	Digital pin type
DNC	Do not connect
GND	Ground
I	Input
Bi	Bidirectional
IPU	Input with internal pull-up
O3S	Tristated signal
ODO	Open-drain output
0	Output
PD	Internal pull-down
SOR	Sample on reset
PWR	Power pin supply
PU	Internal pull-up
XT	Crystal pin type

6.2 Signal Descriptions

6.2.1 13×13 mm² Package

Table 31: Signal Descriptions (13×13 mm² Package)

Signal Name	Type and Default State	Description
PHY Interface	1	
TDP_PHY0_CH0	Bi	TDP_PHY[#]_CH[#], TDN_PHY[#]_CH[#] are transmit/receive pairs. n TRP/
TDN_PHY0_CH0	Bi	N_PHY[port number]_CH[channel number] for 1000BASE-T mode, differential data
TDP_PHY0_CH1	Bi	from the media is transmitted and received on all four signal pairs. In auto-negotiation and 10BASE-T and 100BASE-TX modes, the BCM53158XU normally transmits on
TDN_PHY0_CH1	Bi	TRP/N_PHY[port number]_CH[0] and receives on TRD_PHY[port number]_CH[1].
TDP_PHY0_CH2	Bi	
TDN_PHY0_CH2	Bi	
TDP_PHY0_CH3	Bi	
TDN_PHY0_CH3	Bi	
TDP_PHY1_CH0	Bi	
TDN_PHY1_CH0	Bi	
TDP_PHY1_CH1	Bi	
TDN_PHY1_CH1	Bi	
TDP_PHY1_CH2	Bi	
TDN_PHY1_CH2	Bi	
TDP_PHY1_CH3	Bi	
TDN_PHY1_CH3	Bi	
TDP_PHY2_CH0	Bi	
TDN_PHY2_CH0	Bi	
TDP_PHY2_CH1	Bi	
TDN_PHY2_CH1	Bi	
TDP_PHY2_CH2	Bi	
TDN_PHY2_CH2	Bi	
TDP_PHY2_CH3	Bi	
TDN_PHY2_CH3	Bi	
TDP_PHY3_CH0	Bi	
TDN_PHY3_CH0	Bi	
TDP_PHY3_CH1	Bi	
TDN_PHY3_CH1	Bi	
TDP_PHY3_CH2	Bi	
TDN_PHY3_CH2	Bi	
TDP_PHY3_CH3	Bi	
TDN_PHY3_CH3	Bi	
TDP_PHY4_CH0	Bi	
TDN_PHY4_CH0	Bi	

Table 31: Signal Descriptions (13×13 mm² Package) (Continued)

Signal Name	Type and Default State	Description
TDP_PHY4_CH1	Bi	(Continued)
TDN_PHY4_CH1	Bi	
TDP_PHY4_CH2	Bi	
TDN_PHY4_CH2	Bi	
TDP_PHY4_CH3	Bi	
TDN_PHY4_CH3	Bi	
TDP_PHY5_CH0	Bi	
TDN_PHY5_CH0	Bi	
TDP_PHY5_CH1	Bi	
TDN_PHY5_CH1	Bi	
TDP_PHY5_CH2	Bi	
TDN_PHY5_CH2	Bi	
TDP_PHY5_CH3	Bi	
TDN_PHY5_CH3	Bi	
TDP_PHY6_CH0	Bi	
TDN_PHY6_CH0	Bi	
TDP_PHY6_CH1	Bi	
TDN_PHY6_CH1	Bi	
TDP_PHY6_CH2	Bi	
TDN_PHY6_CH2	Bi	
TDP_PHY6_CH3	Bi	
TDN_PHY6_CH3	Bi	
TDP_PHY7_CH0	Bi	
TDN_PHY7_CH0	Bi	
TDP_PHY7_CH1	Bi	
TDN_PHY7_CH1	Bi	
TDP_PHY7_CH2	Bi	
TDN_PHY7_CH2	Bi	
TDP_PHY7_CH3	Bi	
TDN_PHY7_CH3	Bi	
RESET/Clock		
RESET_L	I, Pu	Hardware Reset Input . Active low Schmitt-triggered input. Resets the BCM53158XU. Active low.
XTAL_P	I	25 MHz Crystal Oscillator Input/Output. A continuous 25 MHz reference clock must
XTAL_N	1	be supplied to the BCM53158XU by connecting a 25 MHz crystal between these two pins or by driving XTALI with a clock. When using a crystal, connect a loading capacitor from each pin to external 25 MHz oscillator GND.
XTAL_CML_P	0	Positive leg of the CML Driver Output from the internal XTAL circuit. Internal debug use only.
XTAL_CML_N	0	Negative leg of the CML Driver Output from the internal XTAL circuit. Internal debug use only.
PLL_TESTP/N	0	DNC, for internal use only.
LCPLL_FREFP/N	0	DNC, for internal use only.

Table 31: Signal Descriptions (13×13 mm² Package) (Continued)

Signal Name	Type and Default State	Description
PLL_TVCO_[2:1]	0	DNC, for internal use only.
RGMII Interface (for po	ort 14)	
IMP_RXCLK	In, Pd	IMPRGMII Interface Receive Clock 125 MHz for 1000 Mb/s operation, 25 MHz for 100 Mb/s operation and 2.5 MHz for 10 Mb/s operation.
IMP_RXD_0	I, Pd	IMP port RGMII Receive Data Inputs. For 1000 Mb/s operation, data bits RXD[3:0] are clocked-out on the rising edge of RXCLK, and data bits RXD[7:4] are clocked on the falling edge of RXCLK. In 10 Mb/s and 100 Mb/s modes, data bits RXD[3:0] are clocked on the rising edge of RXCLK.
IMP_RXD_1	I, Pd	
IMP_RXD_2	I, Pd	
IMP_RXD_3	I, Pd	
IMP_RXDV	I, Pd	IMP port Receive Data Valid. Active high. Indicates the data on the RXD[3:0] pins are encoded and transmitted. Connects to the TXEN of the external MAC/management entity.
IMP_TXCLK	O, Pd	IMP Port RGMII Transmit Clock. This clock is driven to synchronize the transmit data in RGMII mode (125 MHz for 1000 Mb/s operation, 25 MHz for 100 Mb/s operation, and 2.5 MHz for 10 Mb/s operation). In RGMII mode, both edges of the clock are used to align with TXD[3:0].
IMP_TXD_0	O, Pd	IMP Port RGMII Transmit Data Output. For 1000 Mb/s operation, data bits TXD[3:0]
IMP_TXD_1	O, Pd	are clocked on the rising edge of TXCLK, and data bits TXD[7:4] are clocked on the falling edge of TXCLK. For 10 Mb/s and 100 Mb/s, data bits TXD[3:0] are clocked or the rising edge of TXCLK. These output pins have internal 25Ω series termination
IMP_TXD_2	O, Pd	
IMP_TXD_3	O, Pd	resistor.
IMP_TXEN	O, Pd	IMP Port RGMII Transmit Enable
QSGMII Interface for p	orts (BCM53158-Only)	
QSGMII_RDN0	I	QSGMII_Receive Pair
QSGMII_RDP0	I	
QSGMII_TDN0	0	QSGMII Transmit Pair
QSGMII_TDP0	0	
MDC/MDIO Interface		
MDC	Bi, Pd	Management Data I/O. In Master mode, this serial input/output data signal is used to read from and write to the MII registers of the external transceivers. In slave mode, it is used by an external entity to read/write to the switch registers using the pseudo-PHY. See the MDC/MDIO interface for additional information.
MDIO	Bi, Pd	Management Data Clock. In master mode, this 2.5 MHz clock sourced by BCM53158XU to the external PHY device. In Slave mode, it is sources by an external entity.
SPI Interfaces (SPI1 is	an SPI master-only inte	rface; SPI2 is an SPI slave-only interface.)
SCK2 SCK1/en_eee	I, Pu O, Pu	SPI Serial Clock. The clock input to the BCM53158XU SPI interface is supplied by the SPI master, which supports up to 25 MHz; sck1 is used as the strap pin for EN_EEE (Energy Efficient Ethernet). 1'b0 – Disable EEE feature for switch MAC
		■ 1'b1 – Enable EEE feature for switch MAC (default).
SS2 SS1/swd_jtag_sel	I, Pu O, Pu	SPI Slave Select. Active low signal that enables an SPI interface read or write operation. SS1 is also used as the strap pin for CM7DAP operation. ■ 1'b1 − CM7DAP is in JTAG mode ■ 1'b0 − CM7DAP is in SW mode

Table 31: Signal Descriptions (13×13 mm² Package) (Continued)

Signal Name	Type and Default State	Description
MISO2/boot_src0 MISO1	O, Pd I, Pd	SPI Master-In/Slave-Out. Output signal which transmits serial data during an SPI interface read operations. MISO2 is used as the strap pin for boot source selection 1. To set the boot source, use the values below: ■ 2'b00 − Reserved ■ 2'b01 − Reserved ■ 2'b10 − M7 boot from Flash ■ 2'b11 − Boot M7 from internal memory
MOSI2 MOSI1/cascading_config1	I, Pd O, Pd	SPI Master-Out/Slave-In. Input signal which receives control and address information for the SPI interface, as well as serial data during write operations. MOSI1 is used as the strap pin for cascading_config1. To set the cascading_config[1:0] to below operation mode. ■ 2'b00 − Avenger standalone; hardware forwarding (unmanaged) ■ 2'b01 − Avenger cascading enabled; primary ■ 2'b10 − Avenger cascading enabled; secondary ■ 2'b11 − Avenger standalone; no hardware forwarding. NOTE: This signal is tristated during RESET.
JTAG Interface		
TMS	Bi	JTAG Mode Select Input.
TRST_L	Bi	JTAG Test Reset. Active low. Resets the JTAG controller. This signal must be pulled low during normal operation.
TCK	Bi	JTAG Test Clock Input. Clock Input used to synchronize JTAG control and data transfers. If unused, may be left unconnected.
TDI	Bi	JTAG Test Data Input . Serial data input to the JTAG TAP Controller. Sampled on the rising edge of TCK. If unused, may be left unconnected.
TDO	Bi	JTAG Test Data Output . Serial data output to the JTAG TAP Controller. Sampled on the rising edge of TCK. If unused, may be left unconnected.
JTCE0, JTCE1	I	JTAG Capability; select as shown below: 2b'00: DFT LVTAP 2b'01: AVS 2b'10: 8051 debug 2b'11: M7 DAP
LED Interface		
NOTE: LED_[0-7][26][27]: TI low.)	he LED active state is	the inverse of the state of strap setting. LED_[8-25]: The LED active state are always
LED_0/xtal_bypass	O, Pd	LED_0; LED_0 is also used as the strap pin for xtal bypass configuration. 1'b1 – external clock is driven in XTAL pads 1'b0 – crystal is present on board to drive the XTAL pads This strap goes to i_bypass pin of XTAL IP.
LED_1	O, Pd	LED1;
LED_2/xtal_freq_sel	O, Pd	LED2; LED_2 is also used as the strap pin for xtal frequency selection. ■ 1'b1 – 50 MHz XTAL clock ■ 1'b0 – 25 MHz XTAL clock
LED_3/enable_qspi	O, Pd	LED3;LED_3 is also used as the strap pin for QSPI selection. 1'b1 – reserved 1'b0 – QSPI is connected or no connection in SPI0

Table 31: Signal Descriptions (13×13 mm² Package) (Continued)

Signal Name	Type and Default State	Description
LED_4/mdio_vol_sel	O, Pd	LED4; LED_4 is also used as the strap pin for MDIO voltage selection. ■ 1'b0 – 3.3V mode MDIO
LED 5	0.04	1'b1 – 1.2V mode MDIO
LED_5	O, Pd	LED5;
LED_6/mdio_master	O, Pu	LED6; LED_6 is also used as the strap pin for MDIO mode selection. ■ 1'b1 – Avenger is MDIO master ■ 1'b0 – Avenger is MDIO slave (Partial register access) ■ This strap pin must set to 1 for chip normal function and full register access.
LED_7/led_parallel_mode	O, Pd	LED7; LED_7 is also used as the strap pin for LED mode selection. ■ 1'b1 – LED is in parallel mode ■ 1'b0 – LED is in serial mode This strap selects led26/27 as serial led or parallel led.
LED_26_SCLK/ cascading_config0	O, Pd	LED_26_CLK is the LED Shift Clock. This clock is periodically active to enable LEDDATA to shift into external registers.
		LED_26_CLK is used as the strap pin for cascading_config0. To set the cascading_config[1:0] to below operation mode.
		■ 2'b00 – Avenger stand-alone; hardware forwarding(unmanaged)
		2'b01 – Avenger cascading enabled; primary
		 2'b10 – Avenger cascading enabled; secondary 2'b11 – Avenger stand-alone; no hardware forwarding.
LED_27_SDATA/boot_src1	O, Pd	LED_27_SDATA is Serial LED Data Output. Serial LED data for all ports is shifted out when LEDCLK is active. LED_27_SDATA is used as the strap pin for boot source selection 1. To set the boot source, use the values below.
		2'b00 – Reserved
		2'b01 – Reserved2'b10 – M7 boot from Flash
		2'b11 – Boot M7 from internal memory
I ² C Interface		
I2C_SCL	OD	BSC master clock
 I2C_SDA_[13:8]	OD	BSC master data
QSPI Interface		
SS0	0	QUAD-SPI flash
DATA0	Bi	QUAD-SPI flash IO0
DATA1	ВІ	QUAD-SPI flash IO1
DATA2	BI	QUAD-SPI flash IO2
DATA3	BI	QUAD-SPI flash IO3
SCK0 /imp_vol_sel	O, Pd	QUAD-SPI flash; SCK0 is also used as the strap pin for IMP port voltage selection.
		 1'b0 – IMP port works at 2.5V 1'b1 – IMP port works at 1.5V
XFI Interface (for port 12 ar	nd port 13)	
XFI_TDP0	0	XFI Transmit Serial Data, Port 0. Serial data stream signals normally connected to
XFI_TDN0	0	an optical transmitter module. Internal 100Ω differential termination. Requires external A/C coupling.
XFI_TDP1	0	XFI Transmit Serial Data, Port 1. Serial data stream signals normally connected to
XFI_TDN1	0	an optical transmitter module. Internal 100Ω differential termination. Requires external A/C coupling.

Table 31: Signal Descriptions (13×13 mm² Package) (Continued)

Signal Name	Type and Default State	Description
XFI_RDP0	I	XFI Receive Serial Data, Port 0. Serial data stream signals normally connected to an
XFI_RDN0	1	optical receiver module. Internally biased with internal differential 100Ω termination.
XFI_RDP1	I	XFI Receive Serial Data, Port 1. Serial data stream signals normally connected to an
XFI_RDN1	I	optical receiver module. Internally biased with internal differential 100Ω termination.
XFI_REFCLKP/N	1	XFI reference clock, default the 156.25 MHz reference clock of SerDes will be generated by CRU internally. If the XFI needs a clock with less jitter than the internal system clock is providing; it
VEL TECTD/N	0	can provide a clock externally by these two pins.
XFI_TESTP/N	0	DNC; for internal use only
REXT	0	External calibration resistor must connect 4.53 k Ω resistor to GND and place as close as possible to the BGA pin.
MFIO		
MFIO[8:0]	Bi	MultiFunctional I/O. For multiple functions and strap pin function for these pins. See Table 28 on page 66.
Interrupt		
INTR_L	O, Pu	Interrupt. This interrupt pin generates an interrupt based on the configuration in the Interrupt Enable register. It can be programmed to generate based on link status change of any port, or to generate an interrupt to a CPU entity when there is a packet(s) queued in the IMP transmit queue. This signal is active low.
SyncE Interface		
SYNCE_REFCLKOUT	О	Recovered clock outputs from internal source. Can be selected from any of the switch internal cores. For details on mux selection, refer to 5315X-PG10X, CRU TS Core and CRU TS Top registers.
SYNCE_REFCLKOUT_VALID	0	Recovered clock output valid indicators.
SYNCE_RECOV_CLK [1:0]	I	Recovered clock inputs to DPLL function from external source.
SYNCE_RECOV_CLK_VALI D[1:0]	I	Recovered clock inputs to DPLL function valid indicators.
SYNCIN_1588	I	Signal input be used to perform a Freq Sync with an External Source using the HW DPLL inside the Time-Sync Block of switch.
SYNCOUT_1588	0	Signal output from the Time-Sync Block that can be used for synchronization with the receiver of this signal.
Mode Selection		
TESTMODE0	I	Func/Test mode select.
TESTMODE1	I	TESTMODE0 must be low for normal working mode.
TESTMODE2	I	
TESTMODE3	1	
TESTMODE4	I	
Power Interface		
VDDC_1P0	PWR, In	1.0V Digital Core Power (AVS)
VDDO_3P3	PWR, In	3.3V Digital I/O
VSS	_	GND
VDDP_1P8	PWR, In	1.8V input for intermediate state for internal use. (The output is from LDO_VOUT.)
PLL_AVDD	PWR, In	1.8V for PLL
PHY_PLL_VDD1P0_1	PWR, In	1.0V for PHY 0~3 PLL

Table 31: Signal Descriptions (13×13 mm² Package) (Continued)

Signal Name	Type and Default State	Description
PHY_PLL_VDD1P0_2	PWR, In	1.0V for PHY 4~7 PLL
AVDD1P0_PHY_0	PWR, In	1.0V for GPHY I/O 0~3
AVDD1P0_PHY_4	PWR, In	1.0V for GPHY I/O 4~7
AVDD3P3_PHY_0	PWR, In	3.3V for GPHY I/O 0~3
AVDD3P3_PHY_4	PWR, In	3.3V for GPHY I/O 4~7
AVDD_1P8	PWR, In	1.8V analog power
XTAL_AVDD	PWR, In	XTAL power supply 1.8V
BVDD3P3_1	PWR, In	3.3V for GPHY 0~3
BVDD3P3_2	PWR, In	3.3V for GPHY 4~7
SGMII_PVDD1P0	PWR, In	SFI Power Supply 1.0V
SGMII_RVDD1P0	PWR, In	SFI Power Supply 1.0V
SGMII_T_VDD1P0	PWR, In	SFI Power Supply 1.0V
XFI[0:1]_P_VDD1P0	PWR, In	XFI Port Power Supply 1.0V
XFI_T_R_VDD1P0	PWR, In	XFI Port Power Supply 1.0V
MDIO_VDDO	PWR, In	2.5/1.2V I/O power for MDC/MDIO
MDIO_VDDP	PWR, In	1.8/1.2V I/O VDDP doe MDC/MDIO
IMP_VDDO	PWR, In	2.5V/1.5V I/O power for IMP port
IMP_VDDP	PWR, In	1.8V/1.5V I/O VDDP for IMP port
IMP_VOL_REF	PWR, In	GND/0.75V I/O Vref for IMP port
LDO Interface		
LDO_AVDD	PWR, In	3.3V for LDO power input
LDO_VOUT	PWR, Out	1.8V output from LDO. Maximum output current 300 mA.
LDO_VSENSE	PWR, In	1.8V LDO sense in
LDO_AVSS	GND	Ground for LDO
Miscellaneous		
DNP	_	No physical ball (no solder mask)
NC	_	No Connect
PHY_RDC_[2:1]	_	6.04 kΩ resistor to GND is required.
REXT	-	External calibration resistor must connect 4.35 k Ω resistor to GND and place as close as possible to the BGA pin.
PVTMON_ADC PVTMON_DAC	0	Temperature and voltage monitor of internal analog DA/AD converter for internal use only; for internal use only. These two pins are needed to implement the AVS function for 1.0V core voltage. Refer to the Design Guide application note for more detailed information.

Chapter 7: Pin Assignment

7.1 Pin List by Pin Number (13×13 mm²)

Ball No.	Ball Name
A1	VSS
A2	TDN_PHY5_CH3
A3	TDN_PHY5_CH2
A4	TDN_PHY5_CH1
A5	TDN_PHY5_CH0
A6	TDP_PHY6_CH0
A7	TDP_PHY6_CH1
A8	TDP_PHY6_CH2
A9	TDP_PHY6_CH3
A10	TDN_PHY7_CH3
A11	TDN_PHY7_CH2
A12	TDN_PHY7_CH1
A13	TDN_PHY7_CH0
A14	TDP_PHY0_CH0
A15	TDP_PHY0_CH1
A16	TDP_PHY0_CH2
A17	TDN_PHY0_CH3
A18	TDP_PHY1_CH3
A19	VSS
B1	TDN_PHY4_CH3
B2	TDP_PHY5_CH3
B3	TDP_PHY5_CH2
B4	TDP_PHY5_CH1
B5	TDP_PHY5_CH0
B6	TDN_PHY6_CH0
B7	TDN_PHY6_CH1
B8	TDN_PHY6_CH2
B9	TDN_PHY6_CH3
B10	TDP_PHY7_CH3
B11	TDP_PHY7_CH2
B12	TDP_PHY7_CH1
B13	TDP_PHY7_CH0
B14	TDN_PHY0_CH0
B15	TDN_PHY0_CH1
B16	TDN_PHY0_CH2
B17	TDP_PHY0_CH3
B18	TDN_PHY1_CH3

	001 (10 10
Ball No.	Ball Name
B19	TDN_PHY1_CH2
C1	TDP_PHY4_CH3
C2	TDN_PHY4_CH2
C3	TDP_PHY4_CH2
C4	PHY_RDC2
C5	AVDD3P3_PHY_4
C6	AVDD3P3_PHY_4
C7	VSS
C8	VSS
C9	VSS
C10	VSS
C11	VSS
C12	VSS
C13	VSS
C14	AVDD3P3_PHY_0
C15	VSS
C16	PHY_RDC1
C17	TDP_PHY1_CH1
C18	TDN_PHY1_CH1
C19	TDP_PHY1_CH2
D1	DNP
D2	TDN_PHY4_CH1
D3	TDP_PHY4_CH1
D4	VSS
D5	BVDD3P3_2
D6	VSS
D7	VSS
D8	PHYPLL_VDD1P0 _2
D9	AVDD1P0_PHY_4
D10	VSS
D11	AVDD1P0_PHY_0
D12	PHYPLL_VDD1P0 _1
D13	VSS
D14	BVDD3P3_1
D15	AVDD3P3_PHY_0
D16	VSS

Ball No.	Ball Name
D17	TDN_PHY1_CH0
D18	TDP_PHY1_CH0
D19	DNP
E1	TDN_PHY4_CH0
E2	TDP_PHY4_CH0
E3	VSS
E4	VSS
E5	VSS
E6	DNP
E7	DNP
E8	DNP
E9	DNP
E10	DNP
E11	DNP
E12	DNP
E13	DNP
E14	DNP
E15	DNP
E16	TDN_PHY2_CH1
E17	TDP_PHY2_CH1
E18	TDP_PHY2_CH0
E19	TDN_PHY2_CH0
F1	VSS
F2	VSS
F3	VSS
F4	XFI_P_VDD1P0
F5	DNP
F6	VDDC_1P0
F7	VSS
F8	VDDC_1P0
F9	VSS
F10	VDDC_1P0
F11	VDDC_1P0
F12	VDDC_1P0
F13	VSS
F14	VSS
F15	DNP

Ball No.	Ball Name
F16	VSS
F17	TDN_PHY2_CH3
F18	DNP
F19	DNP
G1	XFI_TDP0
G2	XFI_TDN0
G3	VSS
G4	XFI_TESTP
G5	DNP
G6	VDDC_1P0
G7	VSS
G8	VSS
G9	VSS
G10	VSS
G11	VSS
G12	VSS
G13	VSS
G14	LED_5
G15	DNP
G16	LED_0
G17	TDP_PHY2_CH3
G18	TDN_PHY2_CH2
G19	TDP_PHY2_CH2
H1	VSS
H2	VSS
H3	VSS
H4	XFI_TESTN
H5	DNP
H6	VSS
H7	VSS
H8	VSS
H9	VSS
H10	VSS
H11	VSS
H12	VSS
H13	VSS
H14	LED_6

H15 DNP H16 LED_1 H17 TDN_PHY3_CH3 H18 TDP_PHY3_CH3 H19 DNP J1 XFI_RDN0 J2 XFI_RDP0 J3 VSS J4 XFI_R_VDD1P0 J5 DNP J6 VSS J7 VSS J8 VSS J9 VSS J10 VSS J11 VSS J11 VSS J12 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J18 TDP_PHY3_CH2 J19 TDN_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K2 VSS K3 VSS K4 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K11 VSS K12 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0 K16 LED_3 K17 TDP_PHY3_CH0 K17 TDP_PHY3_CH0 K18 TDP_PHY3_CH0 K18 TDP_PHY3_CH0	Ball No.	Ball Name
H16 LED_1 H17 TDN_PHY3_CH3 H18 TDP_PHY3_CH3 H19 DNP J1 XFI_RDN0 J2 XFI_RDP0 J3 VSS J4 XFI_R_VDD1P0 J5 DNP J6 VSS J7 VSS J8 VSS J9 VSS J10 VSS J11 VSS J12 VSS J13 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J19 TDN_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K3 VSS K4 VSS K5 DNP K6 VSS K10 VSS K11 VSS K12 VSS K14 VSS K15		DNP
H17 TDN_PHY3_CH3 H18 TDP_PHY3_CH3 H19 DNP J1 XFI_RDN0 J2 XFI_RDP0 J3 VSS J4 XFI_R_VDD1P0 J5 DNP J6 VSS J7 VSS J8 VSS J9 VSS J10 VSS J11 VSS J12 VSS J13 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J19 TDN_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 <th< td=""><td></td><td></td></th<>		
H18 TDP_PHY3_CH3 H19 DNP J1 XFI_RDN0 J2 XFI_RDP0 J3 VSS J4 XFI_R_VDD1P0 J5 DNP J6 VSS J7 VSS J8 VSS J9 VSS J10 VSS J11 VSS J12 VSS J13 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J18 TDP_PHY3_CH2 J19 TDN_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K2 VSS K3 VSS K4 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	-	_
H19 DNP J1 XFI_RDN0 J2 XFI_RDP0 J3 VSS J4 XFI_R_VDD1P0 J5 DNP J6 VSS J7 VSS J8 VSS J9 VSS J10 VSS J11 VSS J12 VSS J13 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J19 TDN_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 </td <td></td> <td></td>		
J1 XFI_RDN0 J2 XFI_RDP0 J3 VSS J4 XFI_R_VDD1P0 J5 DNP J6 VSS J7 VSS J8 VSS J9 VSS J10 VSS J11 VSS J12 VSS J13 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K3 VSS K4 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP		
J2 XFI_RDP0 J3 VSS J4 XFI_R_VDD1P0 J5 DNP J6 VSS J7 VSS J8 VSS J9 VSS J10 VSS J11 VSS J12 VSS J12 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J18 TDP_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K2 VSS K3 VSS K4 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K11 VSS K12 VSS K11 VSS K12 VSS K13 VSS K14 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K11 VSS K12 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0		
J3 VSS J4 XFI_R_VDD1P0 J5 DNP J6 VSS J7 VSS J8 VSS J9 VSS J10 VSS J11 VSS J12 VSS J13 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K3 VSS K4 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0 <td></td> <td>_</td>		_
J4 XFI_R_VDD1P0 J5 DNP J6 VSS J7 VSS J8 VSS J9 VSS J10 VSS J11 VSS J12 VSS J13 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K10 VSS K11 VSS K12 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0		VSS
J5 DNP J6 VSS J7 VSS J8 VSS J9 VSS J10 VSS J11 VSS J12 VSS J13 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J18 TDP_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K2 VSS K3 VSS K4 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K11 VSS K12 VSS K13 VSS K14 VSS K10 VSS K11 VSS K11 VSS K12 VSS K11 VSS K12 VSS K11 VSS K11 VSS K12 VSS K11 VSS K12 VSS K11 VSS K11 VSS		
J7 VSS J8 VSS J9 VSS J10 VSS J11 VSS J12 VSS J13 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K2 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	J5	
J7 VSS J8 VSS J9 VSS J10 VSS J11 VSS J12 VSS J13 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K2 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	J6	VSS
J8 VSS J9 VSS J10 VSS J11 VSS J12 VSS J13 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K2 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0		VSS
J10 VSS J11 VSS J12 VSS J13 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K2 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0		VSS
J11 VSS J12 VSS J13 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J18 TDP_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	J9	VSS
J11 VSS J12 VSS J13 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J18 TDP_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0		VSS
J13 VSS J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J18 TDP_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K2 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0		VSS
J14 VSS J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J18 TDP_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K2 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K11 VSS K12 VSS K12 VSS K11 TSS K14 VSS K15 DNP	J12	VSS
J15 DNP J16 LED_2 J17 TDN_PHY3_CH2 J18 TDP_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K2 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	J13	VSS
J16 LED_2 J17 TDN_PHY3_CH2 J18 TDP_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K2 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	J14	VSS
J17 TDN_PHY3_CH2 J18 TDP_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K2 VSS K3 VSS K4 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K12 VSS K14 VSS K15 DNP	J15	DNP
J18 TDP_PHY3_CH2 J19 TDN_PHY3_CH1 K1 VSS K2 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K11 VSS K12 VSS K12 VSS K14 VSS K15 DNP	J16	LED_2
J19 TDN_PHY3_CH1 K1 VSS K2 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	J17	TDN_PHY3_CH2
K1 VSS K2 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K12 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	J18	TDP_PHY3_CH2
K2 VSS K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	J19	TDN_PHY3_CH1
K3 VSS K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	K1	VSS
K4 VSS K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	K2	VSS
K5 DNP K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	K3	VSS
K6 VSS K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	K4	VSS
K7 VSS K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	K5	DNP
K8 VSS K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	K6	VSS
K9 VSS K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	K7	VSS
K10 VSS K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	K8	VSS
K11 VSS K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	K9	VSS
K12 VSS K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	K10	VSS
K13 VSS K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	K11	VSS
K14 VSS K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	K12	VSS
K15 DNP K16 LED_3 K17 TDP_PHY3_CH0	K13	VSS
K16 LED_3 K17 TDP_PHY3_CH0	K14	VSS
K17 TDP_PHY3_CH0	K15	DNP
	K16	LED_3
K18 TDN_PHY3_CH0	K17	TDP_PHY3_CH0
	K18	TDN_PHY3_CH0

Ball No.	Ball Name
K19	TDP_PHY3_CH1
L1	XFI_TDN1
L2	XFI_TDP1
L3	VSS
L4	XFI_REFCLKP
L5	DNP
L6	VDDP_1P8
L7	VSS
L8	VSS
L9	VSS
L10	VSS
L11	VSS
L12	VSS
L13	VSS
L14	VDDO_3P3
L15	DNP
L16	LED_4
L17	VSS
L18	VSS
L19	DNP
M1	VSS
M2	VSS
M3	VSS
M4	XFI_REFCLKN
M5	DNP
M6	VDDP_1P8
M7	VSS
M8	VSS
M9	VSS
M10	VSS
M11	VSS
M12	VSS
M13	VSS
M14	VDDO_3P3
M15	DNP
M16	VDDC_1P0
M17	MFIO8
M18	MFIO4
M19	MFIO3
N1	XFI_RDP1
N2	XFI_RDN1
N3	VSS

Ball No.	Ball Name
N4	TESTMODE_0
N5	DNP
N6	VSS
N7	VSS
N8	VSS
N9	VSS
N10	VSS
N11	VSS
N12	VSS
N13	VSS
N14	VSS
N15	DNP
N16	VDDC_1P0
N17	MFIO7
N18	MFIO5
N19	MFIO2
P1	VSS
P2	VSS
P3	VSS
P4	SGMII_P_VDD1P0
P5	DNP
P6	REXT
P7	VSS
P8	VDDC_1P0
P9	VDDC_1P0
P10	VDDC_1P0
P11	VSS
P12	JTCE_0
P13	JTCE_1
P14	VSS
P15	DNP
P16	MFIO6
P17	MFIO0
P18	MFIO1
P19	DNP
R1	QSGMII_RDP0
R2	QSGMII_RDN0
R3	TESTMODE_1
R4	SGMII_R_VDD1P0
R5	DNP
R6	DNP
R7	DNP

Ball No.	Ball Name
R8	DNP
R9	DNP
R10	DNP
R11	DNP
R12	DNP
R13	DNP
R14	DNP
R15	DNP
R16	INTR L
R17	IMP VDDO
R18	IMP VDDP
R19	IMP VOL REF
T1	VSS
T2	VSS
T3	TESTMODE 2
T4	TESTMODE 3
T5	VSS
T6	LDO_VOUT
T7	LDO AVDD
T8	VSS
T9	VDDC_1P0
T10	MDIO VDDO
T11	MDIO VDDP
T12	VDDC_1P0
T13	VDDC 1P0
T14	TDI
T15	TMS
T16	RESET_L
T17	IMP RXDV
T18	IMP_TXD3
T19	IMP_TXCLK
U1	QSGMII_TDN0
U2	QSGMII_TDP0
U3	VSS
U4	XTAL_CML_P
U5	PLL_AVDD
U6	XTAL_AVDD
U7	PVTMON_ADC
U8	TESTMODE_4
U9	MDC
U10	MDIO
U11	MOSI1

Ball No.	Ball Name
U12	MOSI2
U13	SS2
U14	TDO
U15	TCK
U16	IMP RXD1

Ball No.	Ball Name
U17	IMP_RXD3
U18	IMP_TXD2
U19	DNP
V1	VSS
V2	VSS
V3	VSS
V4	XTAL_CML_N
V5	VSS
V6	VSS
V7	PVTMON_DAC
V8	DATA0
V9	DATA2
V10	SCK0
V11	SS1

Ball No.	Ball Name
V12	SCK1
V13	MISO2
V14	TRST_L
V15	LED_26_SLED_CL K
V16	IMP_RXD0
V17	IMP_RXD2
V18	IMP_TXD1
V19	IMP_TXD0
W1	VSS
W2	PLL_TESTN
W3	PLL_TESTP
W4	VSS
W5	XTALN

Ball No.	Ball Name
W6	XTALP
W7	VSS
W8	DATA1
W9	DATA3
W10	DNP
W11	SS0
W12	MISO1
W13	DNP
W14	SCK2
W15	LED_27_SLED_D ATA
W16	DNP
W17	IMP_RXCLK
W18	IMP_TXEN
W19	VSS

7.2 Pin List by Pin Name (13×13 mm²)

Ball No.	Ball Name
D11	AVDD1P0 PHY 0
D9	AVDD1P0_PHY_4
C14	AVDD3P3 PHY 0
D15	AVDD3P3 PHY 0
C5	AVDD3P3 PHY 4
C6	AVDD3P3 PHY 4
D14	BVDD3P3 1
D5	BVDD3P3 2
V8	DATA0
W8	DATA1
V9	DATA2
W9	DATA3
D1	DNP
D19	DNP
E6	DNP
E7	DNP
E8	DNP
E9	DNP
E10	DNP
E11	DNP
E12	DNP
E13	DNP
E14	DNP
E15	DNP
F5	DNP
F15	DNP
F18	DNP
F19	DNP
G5	DNP
G15	DNP
H5	DNP
H15	DNP
H19	DNP
J5	DNP
J15	DNP
K5	DNP
K15	DNP
L5	DNP
L15	DNP
L19	DNP
M5	DNP

Ball No.	Ball Name
M15	DNP
N5	DNP
N15	DNP
P5	DNP
P15	DNP
P19	DNP
R5	DNP
R6	DNP
R7	DNP
R8	DNP
R9	DNP
R10	DNP
R11	DNP
R12	DNP
R13	DNP
R14	DNP
R15	DNP
U19	DNP
W10	DNP
W13	DNP
W16	DNP
W17	IMP_RXCLK
V16	IMP_RXD0
U16	IMP_RXD1
V17	IMP_RXD2
U17	IMP_RXD3
T17	IMP_RXDV
T19	IMP_TXCLK
V19	IMP_TXD0
V18	IMP_TXD1
U18	IMP_TXD2
T18	IMP_TXD3
W18	IMP_TXEN
R17	IMP_VDDO
R18	IMP_VDDP
R19	IMP_VOL_REF
R16	INTR_L
P12	JTCE_0
P13	JTCE_1
T7	LDO_AVDD
T6	LDO_VOUT

Ball No.	Ball Name
G16	LED_0
H16	LED_1
J16	LED_2
V15	LED_26_SLED_CL K
W15	LED_27_SLED_D ATA
K16	LED_3
L16	LED_4
G14	LED_5
H14	LED_6
U9	MDC
U10	MDIO
T10	MDIO_VDDO
T11	MDIO_VDDP
P17	MFIO0
P18	MFIO1
N19	MFIO2
M19	MFIO3
M18	MFIO4
N18	MFIO5
P16	MFIO6
N17	MFIO7
M17	MFIO8
W12	MISO1
V13	MISO2
U11	MOSI1
U12	MOSI2
C16	PHY_RDC1
C4	PHY_RDC2
D12	PHYPLL_VDD1P0 _1
D8	PHYPLL_VDD1P0 _2
U5	PLL_AVDD
W2	PLL_TESTN
W3	PLL_TESTP
U7	PVTMON_ADC
V7	PVTMON_DAC
R2	QSGMII_RDN0
R1	QSGMII_RDP0
U1	QSGMII_TDN0
	1

Ball No.	Ball Name
U2	QSGMII TDP0
T16	RESET L
P6	REXT
V10	SCK0
V10	SCK1
W14	SCK2
P4	SGMII_P_VDD1P0
R4	SGMII_F_VDD1F0
W11	SS0
V11	SS1
U13	SS2
U15	TCK
T14	TDI DUNA CHA
B14	TDN_PHY0_CH0
B15	TDN_PHY0_CH1
B16	TDN_PHY0_CH2
A17	TDN_PHY0_CH3
D17	TDN_PHY1_CH0
C18	TDN_PHY1_CH1
B19	TDN_PHY1_CH2
B18	TDN_PHY1_CH3
E19	TDN_PHY2_CH0
E16	TDN_PHY2_CH1
G18	TDN_PHY2_CH2
F17	TDN_PHY2_CH3
K18	TDN_PHY3_CH0
J19	TDN_PHY3_CH1
J17	TDN_PHY3_CH2
H17	TDN_PHY3_CH3
E1	TDN_PHY4_CH0
D2	TDN_PHY4_CH1
C2	TDN_PHY4_CH2
B1	TDN_PHY4_CH3
A5	TDN_PHY5_CH0
A4	TDN_PHY5_CH1
A3	TDN_PHY5_CH2
A2	TDN_PHY5_CH3
B6	TDN_PHY6_CH0
B7	TDN_PHY6_CH1
B8	TDN_PHY6_CH2
B9	TDN_PHY6_CH3

Ball No.	Ball Name
A13	TDN PHY7 CH0
A12	TDN PHY7 CH1
A12	TDN PHY7 CH2
A10	TDN PHY7 CH3
U14	TDO_FHT7_CH3
	TDP PHY0 CH0
A14	TDP_PHY0_CH0
A15	
A16	TDP_PHY0_CH2
B17	TDP_PHY0_CH3
D18	TDP_PHY1_CH0
C17	TDP_PHY1_CH1
C19	TDP_PHY1_CH2
A18	TDP_PHY1_CH3
E18	TDP_PHY2_CH0
E17	TDP_PHY2_CH1
G19	TDP_PHY2_CH2
G17	TDP_PHY2_CH3
K17	TDP_PHY3_CH0
K19	TDP_PHY3_CH1
J18	TDP_PHY3_CH2
H18	TDP_PHY3_CH3
E2	TDP_PHY4_CH0
D3	TDP_PHY4_CH1
C3	TDP_PHY4_CH2
C1	TDP_PHY4_CH3
B5	TDP_PHY5_CH0
B4	TDP_PHY5_CH1
B3	TDP_PHY5_CH2
B2	TDP_PHY5_CH3
A6	TDP_PHY6_CH0
A7	TDP_PHY6_CH1
A8	TDP_PHY6_CH2
A9	TDP_PHY6_CH3
B13	TDP_PHY7_CH0
B12	TDP_PHY7_CH1
B11	TDP_PHY7_CH2
B10	TDP_PHY7_CH3
N4	TESTMODE_0
R3	TESTMODE_1
T3	TESTMODE_2
T4	TESTMODE_3
U8	TESTMODE_4
	_

Ball No.	Ball Name
T15	TMS
V14	TRST_L
F6	VDDC_1P0
F8	VDDC_1P0
F10	VDDC_1P0
F11	VDDC_1P0
F12	VDDC_1P0
G6	VDDC_1P0
M16	VDDC_1P0
N16	VDDC_1P0
P8	VDDC_1P0
P9	VDDC_1P0
P10	VDDC_1P0
Т9	VDDC_1P0
T12	VDDC_1P0
T13	VDDC_1P0
L14	VDDO_3P3
M14	VDDO_3P3
L6	VDDP_1P8
M6	VDDP_1P8
A1	VSS
A19	VSS
C7	VSS
C8	VSS
C9	VSS
C10	VSS
C11	VSS
C12	VSS
C13	VSS
C15	VSS
D4	VSS
D6	VSS
D7	VSS
D10	VSS
D13	VSS
D16	VSS
E3	VSS
E4	VSS
E5	VSS
F1	VSS
F2	VSS
F3	VSS

Ball No.	Ball Name
F7	VSS
F9	VSS
F13	VSS
F14	VSS
F16	VSS
G3	VSS
G7	VSS
G8	VSS
G9	VSS
G10	VSS
G11	VSS
G12	VSS
G13	VSS
H1	VSS
H2	VSS
H3	VSS
H6	VSS
H7	VSS
H8	VSS
H9	VSS

Ball No.	Ball Name
H10	VSS
H11	VSS
H12	VSS
H13	VSS
J3	VSS
J6	VSS
J7	VSS
J8	VSS
J9	VSS
J10	VSS
J11	VSS
J12	VSS
J13	VSS
J14	VSS
K1	VSS
K2	VSS
K3	VSS
K4	VSS
K6	VSS
K7	VSS
K8	VSS
K9	VSS
K10	VSS
K11	VSS
K12	VSS
K13	VSS
K14	VSS
L3	VSS
L7	VSS
L8	VSS
L9	VSS
L10	VSS
L11	VSS

Ball No.	Ball Name
L12	VSS
L13	VSS
L17	VSS
L18	VSS
M1	VSS
M2	VSS
M3	VSS
M7	VSS
M8	VSS
M9	VSS
M10	VSS
M11	VSS
M12	VSS
M13	VSS
N3	VSS
N6	VSS
N7	VSS
N8	VSS
N9	VSS
N10	VSS
N11	VSS
N12	VSS
N13	VSS
N14	VSS
P1	VSS
P2	VSS
P3	VSS
P7	VSS
P11	VSS
P14	VSS
T1	VSS
T2	VSS
T5	VSS

Ball No.	Ball Name
T8	VSS
U3	VSS
V1	VSS
V2	VSS
V3	VSS
V5	VSS
V6	VSS
W1	VSS
W4	VSS
W7	VSS
W19	VSS
F4	XFI_P_VDD1P0
J4	XFI_R_VDD1P0
J1	XFI_RDN0
N2	XFI_RDN1
J2	XFI_RDP0
N1	XFI_RDP1
M4	XFI_REFCLKN
L4	XFI_REFCLKP
G2	XFI_TDN0
L1	XFI_TDN1
G1	XFI_TDP0
L2	XFI_TDP1
H4	XFI_TESTN
G4	XFI_TESTP
U6	XTAL_AVDD
V4	XTAL_CML_N
U4	XTAL_CML_P
W5	XTALN
W6	XTALP

7.3 Ball Map (13×13 mm² Package)

Figure 20: Ball Map (13×13 mm² Package)

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	
Α	vss	TDN_PHY 5_CH3	TDN_PHY 5_CH2	TDN_PHY 5_CH1	TDN_PHY 5_CH0	TDP_PHY 6_CH0	TDP_PHY 6_CH1	TDP_PHY 6_CH2	TDP_PHY 6_CH3	TDN_PHY 7_CH3	TDN_PHY 7_CH2	TDN_PHY 7_CH1	TDN_PHY 7_CH0	TDP_PHY 0_CH0	TDP_PHY 0_CH1	TDP_PHY 0_CH2	TDN_PHY 0_CH3	TDP_PHY 1_CH3	vss	Α
В	TDN_PHY 4_CH3	TDP_PHY 5_CH3	TDP_PHY 5_CH2	TDP_PHY 5_CH1	TDP_PHY 5_CH0	TDN_PHY 6_CH0	TDN_PHY 6_CH1	TDN_PHY 6_CH2	TDN_PHY 6_CH3	TDP_PHY 7_CH3	TDP_PHY 7_CH2	TDP_PHY 7_CH1	TDP_PHY 7_CH0	TDN_PHY 0_CH0	TDN_PHY 0_CH1	TDN_PHY 0_CH2	TDP_PHY 0_CH3	TDN_PHY 1_CH3	TDN_PHY 1_CH2	В
С	TDP_PHY 4_CH3	TDN_PHY 4_CH2	TDP_PHY 4_CH2	PHY_RDC 2	AVDD3P3 _PHY_4	AVDD3P3 _PHY_4	vss	VSS	VSS	VSS	vss	VSS	VSS	AVDD3P3 _PHY_0	VSS	PHY_RDC 1	TDP_PHY 1_CH1	TDN_PHY 1_CH1	TDP_PHY 1_CH2	С
D	DNP	TDN_PHY 4_CH1	TDP_PHY 4_CH1	vss	BVDD3P3 _2	VSS	vss	PHYPLL_ VDD1P0_ 2	AVDD1P0 _PHY_4	VSS	AVDD1P0 _PHY_0	PHYPLL_ VDD1P0_ 1	vss	BVDD3P3 _1	AVDD3P3 _PHY_0	vss	TDN_PHY 1_CH0	TDP_PHY 1_CH0	DNP	D
E	TDN_PHY 4_CH0	TDP_PHY 4_CH0	vss	vss	vss	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	TDN_PHY 2_CH1	TDP_PHY 2_CH1	TDP_PHY 2_CH0	TDN_PHY 2_CH0	E
F	vss	vss	vss	XFI_P_VD D1P0	DNP	VDDC_1P 0	vss	VDDC_1P	vss	VDDC_1P	VDDC_1P 0	VDDC_1P 0	vss	vss	DNP	vss	TDN_PHY 2_CH3	DNP	DNP	F
G	XFI_TDP0	XFI_TDN0	vss	XFI_TEST P	DNP	VDDC_1P 0	vss	vss	vss	vss	vss	vss	vss	LED_5	DNP	LED_0	TDP_PHY 2_CH3	TDN_PHY 2_CH2	TDP_PHY 2_CH2	G
Н	vss	vss	vss	XFI_TEST N	DNP	vss	vss	vss	vss	vss	vss	vss	vss	LED_6	DNP	LED_1	TDN_PHY 3_CH3	TDP_PHY 3_CH3	DNP	Н
J	XFI_RDN 0	XFI_RDP0	vss	XFI_R_VD D1P0	DNP	vss	vss	vss	vss	vss	vss	vss	vss	vss	DNP	LED_2	TDN_PHY 3_CH2	TDP_PHY 3_CH2	TDN_PHY 3_CH1	J
к	vss	vss	vss	vss	DNP	vss	vss	vss	vss	vss	vss	vss	vss	vss	DNP	LED_3	TDP_PHY 3_CH0	TDN_PHY 3_CH0	TDP_PHY 3_CH1	К
L	XFI_TDN1	XFI_TDP1	vss	XFI_REF CLKP	DNP	VDDP_1P 8	vss	vss	vss	vss	vss	vss	vss	VDDO_3P	DNP	LED_4	vss	vss	DNP	L
М	vss	vss	vss	XFI_REF CLKN	DNP	VDDP_1P 8	vss	vss	vss	vss	vss	vss	vss	VDDO_3P	DNP	VDDC_1P 0	MFIO8	MFIO4	MFIO3	М
N	XFI_RDP1	XFI_RDN 1	VSS	TESTMO DE_0	DNP	VSS	vss	VSS	VSS	VSS	vss	VSS	vss	VSS	DNP	VDDC_1P 0	MFIO7	MFIO5	MFIO2	N
Р	vss	vss	vss	SGMII_P_ VDD1P0	DNP	REXT	vss	VDDC_1P 0	VDDC_1P	VDDC_1P 0	vss	JTCE_0	JTCE_1	vss	DNP	MFIO6	MFIO0	MFIO1	DNP	Р
R	QSGMII_ RDP0	QSGMII_ RDN0	TESTMO DE_1	SGMII_R_ VDD1P0	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	DNP	INTR_L	IMP_VDD O	IMP_VDD P	IMP_VOL _REF	R
т	vss	vss	TESTMO DE_2	TESTMO DE_3	vss	LDO_VO UT	LDO_AVD D	vss	VDDC_1P 0	MDIO_VD DO	MDIO_VD DP	VDDC_1P 0	VDDC_1P 0	TDI	TMS	RESET_L	IMP_RXD V	IMP_TXD 3	IMP_TXC LK	Т
U	QSGMII_T DN0	QSGMII_T DP0	vss	XTAL_CM L_P	PLL_AVD D	XTAL_AV DD	PVTMON _ADC	TESTMO DE_4	MDC	MDIO	MOSI1	MOSI2	SS2	TDO	тск	IMP_RXD 1	IMP_RXD 3	IMP_TXD	DNP	U
٧	vss	vss	vss	XTAL_CM L_N	vss	vss	PVTMON _DAC	DATA0	DATA2	SCK0	SS1	SCK1	MISO2	TRST_L	LED_26_ SLED_CL K	IMP_RXD 0	IMP_RXD 2	IMP_TXD 1	IMP_TXD 0	٧
w	vss	PLL_TES TN	PLL_TES TP	vss	XTALN	XTALP	vss	DATA1	DATA3	DNP	SS0	MISO1	DNP	SCK2	LED_27_ SLED_DA TA	DNP	IMP_RXC LK	IMP_TXE N	vss	w
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	

Chapter 8: Electrical Characteristics

8.1 Absolute Maximum Ratings

Table 32: Absolute Maximum Ratings^a

Parameter	Symbol	Min.	Max.	Unit
3.3V Supply Voltage	VDDO_3P3, AVDD3P3_PHY0, AVDD3P3_PHY1 AVDD3P3_PHY2, AVDD3P3_PHY3, BVDD3P3	-0.5	+3.63	V
	LDO_AVDD, MDIO_VDDOb			
2.5V Supply Voltage	RGMII_VDDO ^c	-0.5	+2.75	V
1.5V Supply Voltage	RGMII VDDO ^c , RGMII VDDP ^c	-0.5	+1.65	V
1.8V Supply Voltage	VDDP_1P8, OTP_VDD, AVDD_PVTMON, PLL_VDD1P8, XTAL_VDD1P8, UPI_VDD18 UPI_VDD18_int RGMII_VDDP ^c , MDIO_VDDP ^b	-0.5	+1.98	V
1.2V Supply Voltage	DDR_VDDO, DDR_VDDO_CK MDIO_VDDO ^b ,MDIO_VDDP ^b	-0.5	+1.32	V
1.0V Supply Voltage	VDDC_1P0, AVDD0P9_PHY0, AVDD0P9_PHY1 AVDD0P9_PHY2, AVDD0P9_PHY3, PHYPLL_VDD0P9, QSGMII_P_R_VDD1P0 QSGMII_T_VDD1P0, XFI_P_R_VDD1P0 XFI_T_VDD1P0, RESCAL_pad_i_VDD1p0	-0.5	+1.1	V
Maximum Junction Temperature	T_{J_MAX}	_	+110	°C
Commercial Ambient Temperature (Operating)	T _A	0	+70	°C
Industrial Ambient Temperature (Operating)	TA	-40	+85	°C
Operating Humidity	-	_	+85	%
Storage Temperature	T _{STG}	-40	+125	°C
Storage Humidity	-	_	60	%

a. These specifications indicate levels where permanent damage to the device may occur. Functional operation is not guaranteed under these conditions. Operation at maximum conditions for extended periods may adversely affect long-term reliability of the device.

c. RGMII interface for 2.5V/1.5V.

b. MDC/MDIO for 3.3V/1.2V.

8.2 Recommended Operating Conditions and DC Characteristics

NOTE: Refer to *BCM53158XU Hardware Design Guide* for more information on voltage tolerances and power supplies decoupling.

NOTE: The voltage tolerances are ±3% on 1.0V and ±5% on all other supplies. The 1.0V ±3% does not apply to VDDC_1P0 (AVS). The actual voltage level and tolerance on the VDDC_1P0 supply is controlled by AVS. AVS is required for the device to operate properly and the voltage range is 0.85V to 1.10V.

Table 33: Recommended Operating Conditions

Symbol	Nominal Value	Description
VDDC_1P0	1.0V	1.0V core power (AVS)
AVDD0P9_PHY0	1.0V	1.0V analog power (GPHY)
AVDD0P9_PHY1	1.0V	
AVDD0P9_PHY2	1.0V	
AVDD0P9_PHY3	1.0V	
PHYPLL_VDD0P9	1.0V	1.0V PLL power for GPHY
QSGMII_P_R_VDD1P0	1.0V	1.0V power supply for QSGMII
QSGMII_T_VDD1P0	1.0V	
XFI_P_R_VDD1P0	1.0V	1.0V power supply for Eagle
XFI_T_VDD1P0	1.0V	
RESCAL_pad_i_VDD1p0	1.0V	1.0V power for RESCAL (non-AVS)
UPI_VDD18_int	1.8V	1.8V power for UPI
UPI_VDD18	1.8V	
PLL_VDD1P8	1.8V	1.8V System PLL power. (for both PLL1 and LCPLL)
AVDD_PVTMON	1.8V	1.8V pvtmon power supply
XTAL_VDD1P8	1.8V	1.8V power for XTAL
OTP_VDD	1.8V	1.8V OTP power
VDDP_1P8	1.8V	1.8V general I/O VDDP power
MDIO_VDDP	1.8/1.2V	1.8/1.2V I/O VDDP doe MDC/MDIO
RGMII_VDDP	1.8V/1.5V	1.8V/1.5V I/O VDDP for WAN port
MDIO_VDDO	3.3/1.2V	3.3/1.2V I/O power for MDC/MDIO
VDDO_3P3	3.3V	3.3V general I/O power
AVDD3P3_PHY0	3.3V	3.3V analog power (GPHY)
AVDD3P3_PHY1	3.3V	
AVDD3P3_PHY2	3.3V	
AVDD3P3_PHY3	3.3V	
BVDD3P3	3.3V	3.3V BIAS power for GPHY
LDO_AVDD	3.3V	3.3V power for LDO
RGMII_VDDO	2.5V/1.5V	2.5V/1.5V I/O power for WAN port (PAD_wan_*).

8.2.1 Standard 3.3V Signals

These specifications apply to all 3.3V signals, such as Serial Flash, MII, MFIO, I²C, MDC/MDIO, SyncE pins, JTAG interfaces, and clock reset pins.

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input voltage	V _{IN}	_	-0.3	_	3.63	
Input low voltage	V _{IL}	_	_	_	0.8	V
Input high voltage	V _{IH}	_	2.0	_	_	V
Output low voltage	V _{OL}	IOL = 4 mA	_	_	0.4	V
Output low current	I _{OL}	VOL = 0.4V	4.0	_	_	mA
Output high voltage	V _{OH}	IOH = -4 mA	2.4	_	_	V

8.2.2 Standard 2.5V Signals

These specifications apply to all 2.5V signals, such as RGMII interface.

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input voltage	V _{IN}	_	-0.3	_	2.75	
Input low voltage	V _{IL}	_	_	_	0.8	V
Input high voltage	V _{IH}	_	1.7	_	_	V
Output low voltage	V _{OL}	_	_	_	0.4	V
Output high voltage	V _{OH}	_	2.0	_	_	V

8.2.3 REFCLK Input Timing

Table 34: REFCLK Input Timing

Parameter	Symbol	Min.	Тур.	Max.	Unit
Frequency	C _{freq}	_	25	_	MHz
Accuracy	_	-15	_	+15	ppm
RMS Jitter (noise bandwidth: 10 kHz – 5 MHz)	_	_	0.444	0.651	ps
RMS Jitter (noise bandwidth: 10 kHz – 1 MHz)	_	_	0.281	0.392	ps
ESR	_	_	_	15	ohm
Frequency	C _{freq}	_	156.25	_	MHz
Accuracy	_	-50	_	+50	ppm
RMS Jitter	_	_	_	0.7	ps
Rise/Fall time (20%~80%)	T_r/T_f	_	200	300	ps

8.2.4 QSGMII Transmitter

Table 35: QSGMII Transmitter

Parameter	Symbol	Min.	Тур.	Max.	Unit
Baud Rate	T _{Baud}	-	5.000	_	Gsym/s

Table 35: QSGMII Transmitter (Continued)

Parameter	Symbol	Min.	Тур.	Max.	Unit
Output Differential Voltage	T _{DIFF}	400	-	1200	mVppd
(into floating Load R _{load} =100 ohm)					
Differential Resistance	T _{RD}	80	100	120	Ohms
Recommended Output Rise and Fall Time (20% to 80%)	T _R / T _F	30	_	_	Ps
Transmitter Common Mode Noise	TN _{CM}	_	_	5% of T _{DIFF}	mVppd
Output current short	T _{IS}	_	100	mA	_
Output Common Mode Voltage	T _{CM}	735	-	1135	_
Output Amplitude	_	_	_	_	_

8.2.5 QSGMII Receiver

Table 36: QSGMII Receiver

Parameter	Symbol	Min.	Тур.	Max.	Unit
Baud Rate	R _{Baud}	-	5.0	_	Gsym/s
Output Differential Voltage	R _{DIFF}	100	_	750	mVppd
(into floating Load R_{load} =100 Ω)					

8.2.6 XFI Transmitter Performance Specification

Figure 21: XFI Far-End Eye Mask

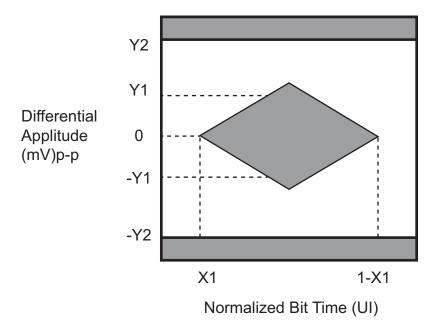


Table 37: XFI Far-End Eye Mask

Parameter	Min.	Тур.	Max.	Unit
Nominal VCO center frequency	_	10.3125	_	_
Total jitter	_	_	0.61	_
Total non-EQJ Jitter	_	_	0.41	_
Eye mask X1	_	_	0.305	UI
Eye mask Y1	60	_	_	mV
Eye mask Y1	_	_	410	mV

8.2.7 XFI Transmitter DC Characteristics

Table 38: XFI Transmitter DC Characteristics

Parameter	Symbol	Min.	Тур.	Max.	Unit
Output Voltage, differential	V _{od1V}	0.5	1.0	1.1	V_{ptpd}
Output Voltage, common mode	V _{ocm}	_	0.5	_	V
Output Voltage fall time (20% to 80%)	t _{fall}	24	_	47	ps
Output Voltage rise time (20% to 80%)	t _{rise}	24	_	47	Ps

8.2.8 XFI Receiver Input Performance Specification

Table 39: XFI Receiver Input Performance Specification

Parameter	Min.	Тур.	Max.	Unit
Total jitter	_	_	0.65	UI
Total non-EQJ Jitter	_	_	0.45	UI
Eye mask X1	_	_	0.325	UI
Eye mask Y1	55	_	_	mV
Eye mask Y2	_	_	525	mV

8.2.9 XFI Receiver DC Characteristics

Table 40: XFI Receiver DC Characteristics

Parameter	Symbol	Min.	Тур.	Max.	Unit
Input Voltage, differential	V _{id}	85	_	1600	mVppd
Input Voltage, common mode	V _{CM-RX}	400	750	1100	mV
Input voltage, peak	V _{max-RX}	0	_	1500	mV

8.2.10 RGMII Pin Operation at 2.5V VDDO_RGMII

Table 41: RGMII Pin Operation at 2.5V VDDO_RGMII

Parameter	Symbol	Min.	Max.	Unit	Condition
Input high voltage, RGMII pin	V _{IH}	1.70	OVDD_RGMII	V	_

Table 41: RGMII Pin Operation at 2.5V VDDO_RGMII (Continued)

Parameter	Symbol	Min.	Max.	Unit	Condition
Input low voltage, RGMII pin	V _{IL}	-0.30	+0.70	V	_
Output high voltage, RGMII pin	V _{OH}	2.0	_	V	I _{OH} = -1 mA
Output low voltage, RGMII pin	V _{OL}	_	0.4	V	I _{OL} = 1 mA

8.2.11 RGMII Pin Operation at 1.5V VDDO_RGMII

Table 42: RGMII Pin Operation at 1.5V VDDO_RGMII

Parameter	Symbol	Min.	Max.	Unit	Condition
Input high voltage, RGMII pin	V _{IH}	0.5xOVDD_RGMII+0.1	OVDD_RGMII	V	HSTL
Input low voltage, RGMII pin	V_{IL}	-0.30	0.5xOVDD_RGMII-0.1	V	HSTL
Output high voltage, RGMII pin	V _{OH}	OVDD_RGMII-0.4	_	V	HSTL
Output low voltage, RGMII pin	V _{OL}	_	0.4	V	HSTL

8.3 Power Consumption

8.3.1 Power Consumption

Table 43: BCM53158X Estimated Power Consumption

	Measured Power Consumption									
Symbol	Part	Power Rail	Conditions	Min.	Typical	Max.	Unit			
Blocks	BCM53158X	Core VDD	Measured	_	_	1.923667	W			
		1V Analog	Measured	_	_	0.775333	W			
		3.3V	Measured	_	_	1.862	W			
		2.5V	Measured	_	_	0.081	W			
		1.8V	Measured	_	_	0.100667	W			
Total			Measured	_	_	4.742667	W			

This maximum power consumption was measured with below worst case conditions:

- 33G full traffic running with all interfaces
- Junction Temperature (T_i) @ 110°C
- AVS running for VDDC_1P0

Chapter 9: Timing Characteristics

9.1 Reset and Clock Timing

Figure 22: Reset and Clock Timing

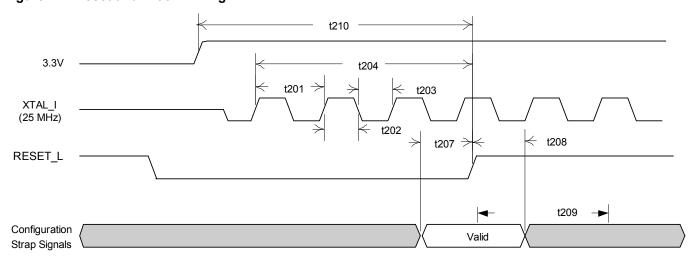


Table 44: Reset and Clock Timing

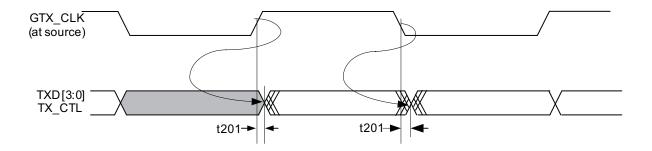
Parameter	Description	Minimum	Typical	Maximum	Unit
t201	XTAL_I frequency	_	25.0000	_	MHz
t202	XTAL_I high time	_	20	_	ns
t203	XTAL_I low time	_	20	_	ns
t204	RESET_L low pulse duration	50	_	_	ms
t207	Configuration valid setup to RESET_L rising	50	_	_	μs
t208	Configuration valid hold from RESET_L rising	120	_	_	ns
t209	RESET_L deassertion to normal operation	_	1.0	_	ms
t210	Reset low hold time after power supplies stabilize	100	_	_	ms

9.2 RGMII Interface Timing

The following specifies timing information regarding the IMP interface pins when configured in RGMII mode.

9.2.1 RGMII Output Timing (Normal Mode)

Figure 23: RGMII Output Timing (Normal Mode)



NOTE: Advanced timing extracted from statistical data. It may or may not reflect the true timing of the device.

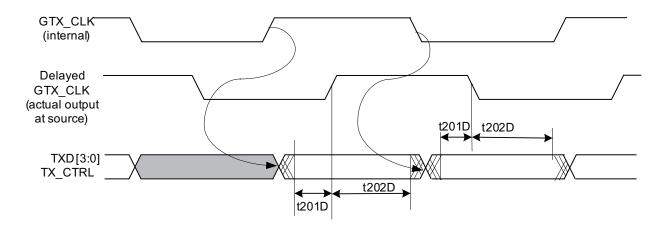
Table 45: RGMII Output Timing (Normal Mode)

Description	Parameter	Minimum	Typical	Maximum	Unit
MII1_TXC clock period (1000M mode)	_	7.2	8	8.8	ns
MII1_TXC clock period (100M mode)	_	36	40	44	ns
MII1_TXC clock period (10M mode)	_	360	400	440	ns
TskewT: Data to clock output skew	t201	-500 (1000M)	0	+500 (1000M)	ps
TskewT: Data to Clock at 1.5V mode	t201	-750 (1000M)	0	+500 (1000M)	ps
Duty cycle for 1000M (GE)	_	45	50	55	%
Duty cycle for 10/100M (FE)	_	40	50	60	%

NOTE: The output timing in 10/100M operation is always as specified in the delayed mode.

9.2.2 RGMII Output Timing (Delayed Mode)

Figure 24: RGMII Output Timing (Delayed Mode)



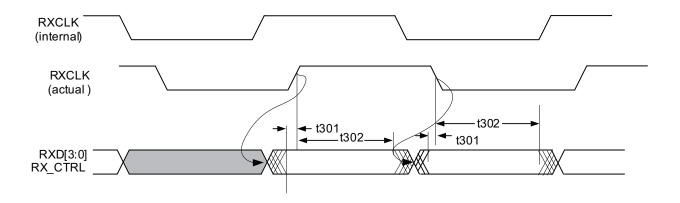
NOTE: Advanced timing extracted from statistical data. It may or may not reflect the true timing of the device.

Table 46: RGMII Output Timing (Delayed Mode)

Description	Parameter	Minimum	Typical	Maximum	Unit
MII1_TXC clock period (1000M mode)	_	7.2	8	8.8	ns
MII1_TXC clock period (100M mode)	_	36	40	44	ns
MII1_TXC clock period (10M mode)	_	360	400	440	ns
TsetupT Data valid to clock transition: Available setup time at the output source (delayed mode)	t201D	1.2 (all speeds)	2.0	-	ns
TholdT Clock transition to data valid: Available hold time at the output source (delayed mode)	t202D	1.2 (all speeds)	2.0	-	ns
TsetupT Data valid to clock transition: Available setup time at the output source (1.5V mode)	t201D	1.0 (all speeds)	2.0	_	ns
TholdT Clock transition to data valid: Available hold time at the output source (1.5V mode)	t202D	1.0 (all speeds)	2.0	-	ns
Duty cycle for 1000M (GE)	_	45	50	55	%
Duty cycle for 10/100M (FE)	_	40	50	60	%

9.2.3 RGMII Input Timing (Normal Mode)

Figure 25: RGMII Input Timing (Normal Mode)



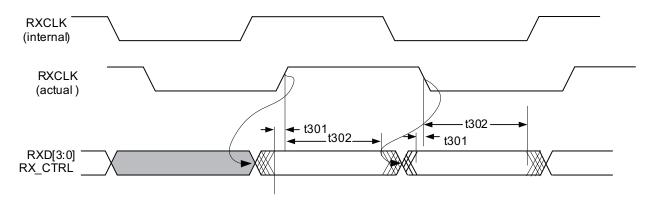
NOTE: Advanced timing extracted from statistical data. It may or may not reflect the true timing of the device.

Table 47: RGMII Input Timing (Normal Mode)

Description	Parameter	Minimum	Typical	Maximum	Unit
MII1_RXC clock period (1000M mode)	_	7.2	8	8.8	ns
MII1_RXC clock period (100M mode)	_	36	40	44	ns
MII1_RXC clock period (10M mode)	_	360	400	440	ns
TsetupR Input setup time: Valid data to clock	t301	1.0	2.0	_	ns
TholdR Input hold time: Clock to valid data	t302	1.0	2.0	_	ns
Duty cycle for 1000M (GE)	_	45	50	55	%
Duty cycle for 10/100M (FE)	_	40	50	60	%

9.2.4 RGMII Input Timing (Delayed Mode)

Figure 26: RGMII Input Timing (Delayed Mode)



NOTE: Advanced timing extracted from statistical data. It may or may not reflect the true timing of the device.

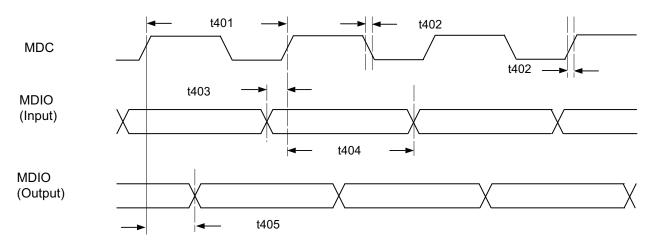
Table 48: RGMII Input Timing (Delayed Mode)

Description	Parameter	Minimum	Typical	Maximum	Unit
TsetupR	t301D	-1.0 (1000M)	_	_	ns
Input setup time (delayed mode)		-1.0 (10/100M)	_	_	ns
TholdR	t302D	3.0 (1000M)	_	_	ns
Input hold time (delayed mode)		9.0 (10/100M)	ı	1	ns

9.3 MDC/MDIO Timing

The following specifies timing information regarding the MDC/MDIO interface pins.

Figure 27: MDC/MDIO Timing (Slave Mode)



NOTE: Advanced timing extracted from statistical data. It may or may not reflect the true timing of the device.

Table 49: MDC/MDIO Timing (Slave Mode)

Description	Parameter	Minimum	Typical	Maximum	Unit
MDC cycle time	t401	80	-	-	ns
MDC high/low	_	30	-	-	ns
MDC rise/fall time	t402	-	-	10	ns
MDIO input setup time to MDC rising	t403	7.5	-	-	ns
MDIO input hold time from MDC rising	t404	7.5	-	_	ns
MDIO output delay from MDC rising	t405	0	_	45	ns

Figure 28: MDC/MDIO Timing (Master Mode)

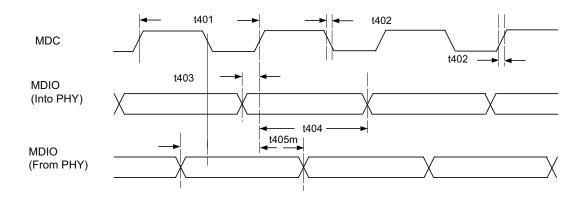


Table 50: MDC/MDIO Timing (Master Mode)

Description	Parameter	Minimum	Typical	Maximum	Unit
MDC cycle time	t401	400	_	_	ns
MDC high/low	_	160	_	240	ns
MDC rise/fall time	t402	_	_	10	ns
MDIO input setup time to MDC rising	t403	20	_	_	ns
MDIO input hold time from MDC rising	t404	7.5	_	_	ns
MDIO output delay from MDC rising	t405	0	_	30	ns

9.4 Serial Flash Timing

Figure 29: Serial Flash Timing Diagram

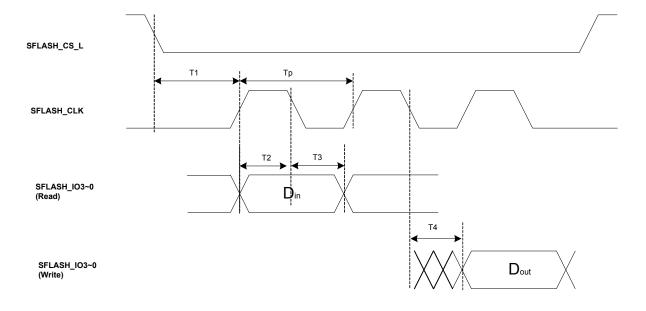


Table 51: Serial Flash Timing

Parameter	Descriptions	Min.	Тур.	Max.	Unit
f _{FREQ}	SFlash_CLK frequency	_	_	62.5	MHz
t _P	Cycle time: SFLASH_CLK period	16	_	_	ns
t ₁	Delay time: SFLASH_CS_L low to SFLASH_CLK rising edge	_	1	-	t _P
t ₂	Input Setup time: SFLASH_IOx valid to SFLASH_CLK falling edge	10	_	-	ns
t ₃	Input Hold time: SFLASH_CLK falling edge to SFLASH_IOx invalid	0	_	_	ns
t ₄	Output valid time: SFLASH_IOx valid to SFLASH_CLK rising edge	6	_	-	ns

9.5 SPI Interface Timing

9.5.1 BCM53158XU SPI-1 Master Interface Timing (A1)

Figure 30: SPI-1 Timing, SS Asserted During SCK Low

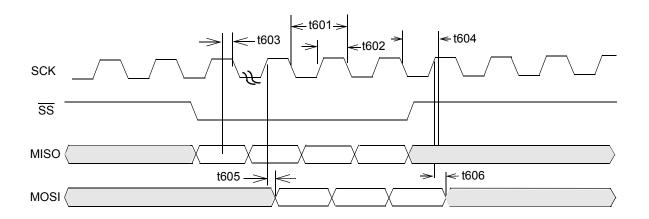


Table 52: SPI-1 Timing

Parameter	Description	Minimum	Typical	Maximum	Unit
t601	SCK Clock Period	40	_	_	ns
t602	SCK High/Low Time	-	_	_	ns
t603	MISO to SCK Setup Time	7	-	_	ns
t604	MISO to SCK Hold Time	0	_	_	ns
t605	SCK to MOSI Valid	-	_	6	ns
t606	SCK to MOSI Invalid	0		_	ns

9.5.2 BCM53158XU SPI-2 Slave Interface Timing (A1)

Figure 31: SPI-2 Timing, SS Asserted During SCK Low

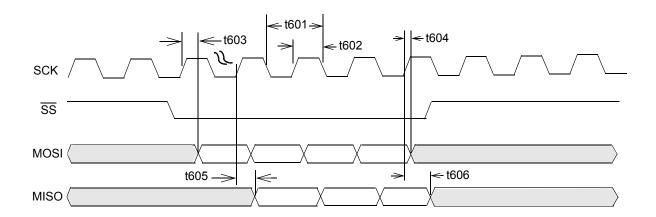


Table 53: SPI-2 Timing

Parameter	Description	Minimum	Typical	Maximum	Unit
t601	SCK Clock Period	40	_	_	ns
t602	SCK High/Low Time	_	-	_	ns
t603	MOSI to SCK Setup Time	5	_	_	ns
t604	MOSI to SCK Hold Time	3	-	_	ns
t605	SCK to MISO Valid	_	-	7	ns
t606	SCK to MISO Invalid	0	_	_	ns

9.5.3 BCM53158XU SPI-1 Master Interface Timing (B0)

Figure 32: SPI-1 Timing, SS Asserted During SCK High

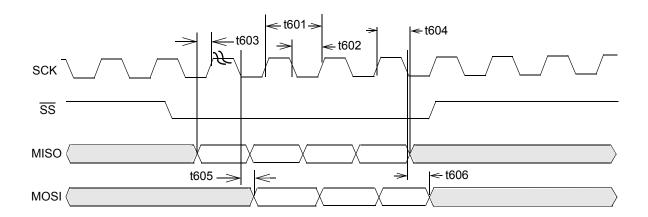


Table 54: SPI-1 Timing

Parameter	Description	Minimum	Typical	Maximum	Unit
t601	SCK Clock Period	40	_	_	ns
t602	SCK High/Low Time	_	_	_	ns
t603	MISO to SCK Setup Time	7	_	_	ns
t604	MISO to SCK Hold Time	0	_	_	ns
t605	SCK to MOSI Valid	_	_	6	ns
t606	SCK to MOSI Invalid	0	_	_	ns

9.5.4 BCM53158XU SPI-2 Slave Interface Timing (B0)

Figure 33: SPI-2 Timing, SS Asserted During SCK High

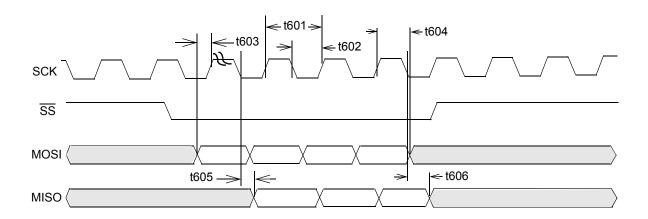


Table 55: SPI-2 Timing

Parameter	Description	Minimum	Typical	Maximum	Unit
t601	SCK Clock Period	40	_	_	ns
t602	SCK High/Low Time	-	_	_	ns
t603	MOSI to SCK Setup Time	5	_	_	ns
t604	MOSI to SCK Hold Time	3	-	_	ns
t605	SCK to MISO Valid	_	_	7	ns
t606	SCK to MISO Invalid	0	_	_	ns

9.6 JTAG Interface

JTAG timing is synchronous to the JTAG_TCK clock.

Figure 34: JTAG Interface

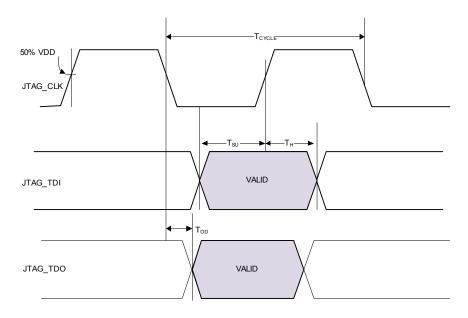


Table 56: JTAG Interface

Parameter	Description	Min.	Тур.	Max.	Unit
TCYCLE	JTAG Cycle Time	50		_	ns
Tsu	Input Setup Time	12.5	-	_	ns
Тн	Input Hold Time	12.5	-	_	ns
Tod	Output Delay Time Measured from Falling Edge of JTAG_TCK	-	-	22	ns

9.7 BSC Timing

Figure 35: BSC Interface

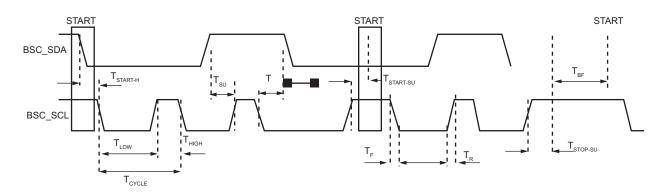


Table 57: BSC Interface

Parameter	Description	Min.	Тур.	Max.	Unit
TCYCLE	BSC_SCL Cycle Time	10	1	100	ns

Table 57: BSC Interface (Continued)

Parameter	Description	Min.	Тур.	Max.	Unit
TLOW	BSC_SCL Low Time	4.7	_	_	ns
Тнідн	BSC_SCL High Time	4.0	_	_	ns
Тн	Data Hold Time	300	_	_	ns
Tsu	Data Setup Time	250	_	_	ns
Tr	Rise Time (Clock and Data, see note below)	_	_	1000	ns
TF	Fall Time (Clock and Data)	_	_	300	ns
TSTART-H	Hold Time, START, or Repeated START	4.0	_	_	ns
TSTART-SU	Setup Time, Repeated START	4.7	_	_	ns
TSTOP-SU	Setup Time, STOP	4.0	_	_	ns
TBF	Bus Free Time Between STOP and START	4.7	_	_	ns

NOTE:

- BSC_SCL and BSC_SDA are open-collector outputs. The rise time is dependent on the strength of the external pull-up resistor, which is recommended to be chosen to meet the rise time requirement.
- BSC = Broadcom Serial Controller master mode only. It is compatible with I²C standard. I²C is copyrighted by Philips/NXP.

9.8 Serial LED Interface Timing

The following specifies timing information regarding the LED interface pins.

Figure 36: LEDCLK/LEDDATA Timing

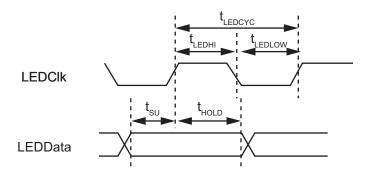


Figure 37: LEDClk/LEDData Refresh Interval

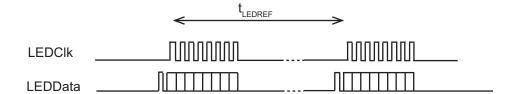


Table 58: Serial LED Timing

Parameter	Description	Min.	Тур.	Max.	Unit
t _{LEDCYC}	LED clock period	-	200	-	ns
t _{LEDHI}	LED clock high-pulse width	70	100	130	ns
t _{LEDLOW}	LED clock low-pulse width	70	100	130	ns
t _{su}	LED data setup time	50	90	_	ns
t _{HOLD}	LED data hold time	50	90	_	ns
t _{LEDREF}	LED refresh period	-	30	-	ms

9.9 SGMII/SerDes Timing

Figure 38: SGMII/SerDes Interface Output Timing

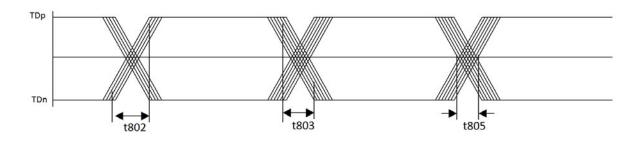


Table 59: SGMII/SerDes Interface Output Timing

Parameter	Description	Min.	Тур.	Max.	Unit
t801	Transmit Data Signaling Speed	_	1.25	_	Gbaud
t802	Transmit Data Rise Time (20% to 80%)	100	_	200	ps
t803	Transmit Data Fall Time (20% to 80%)	100	_	200	ps
t805	Transmit Data Total Jitter	_	_	0.25	UI

Figure 39: SGMII/SerDes Interface Input Timing

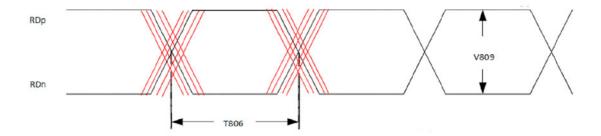


Table 60: SGMII/SerDes Interface Input Timing

Parameter	Description	Min.	Тур.	Max.	Unit
t806	Receive Data Signaling Speed	_	3.125	-	Gbaud
v809	Receive Data Differential Input (pk-pk)	0.1	_	2.0	V

9.10 2.5GE/SerDes Timing

Figure 40: 2.5GE/SerDes Interface Output Timing

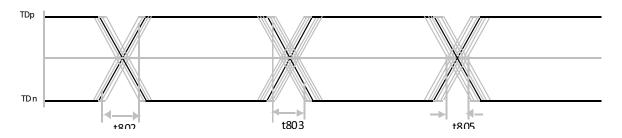


Table 61: 2.5GE/SerDes Interface Output Timing

Parameter	Description	Min.	Тур.	Max.	Unit
t801	Transmit Data Signaling Speed	_	3.125	_	Gbaud
t802	Transmit Data Rise Time (20% to 80%)	30	-	130	ps
t803	Transmit Data Fall Time (20% to 80%)	30	-	130	ps
t805	Transmit Data Total Jitter	_	-	0.35	UI
T _{SKEW}	Transmit Differential Skew	_	-	0.15	ps

Figure 41: 2.5GE/SerDes Interface Input Timing

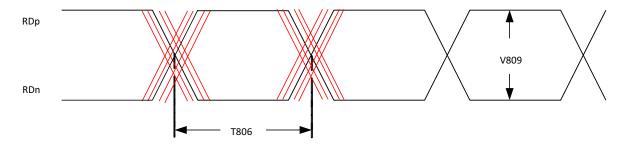


Table 62: 2.5GE/SerDes Interface Input Timing

Parameter	Description	Min.	Тур.	Max.	Unit
t806	Receive Data Signaling Speed	_	3.125	-	Gbaud
v809	Receive Data Differential Input (pk-pk)	_	_	1.6	V

9.11 Synchronous Ethernet Interface

TBD

Chapter 10: Thermal Characteristics

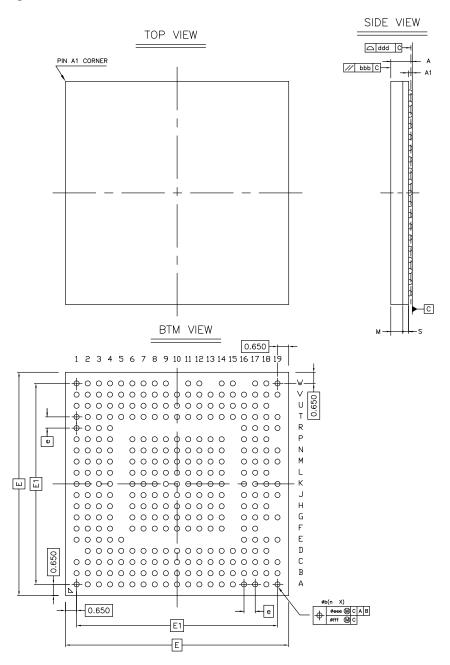
10.1 BCM53156XU/BCM53158XU Package with Heat Sink (35×35×15 mm³)

Table 63: 13x13 mm² Package with External Heat Sink 35x35x15 mm³, 2s2p PCB, T_A = 50°C, P = 4.566W

Device power dissipation, P (W) Ambient air temperature, T_A (°C) θ_{JA} in still air (°C/W)			4.566				
			50.0 13.74				
θ _{JC} (°C/W)	(°C/W) 4.25						
2s2p board	, 35x5x15 mm ³ estH	S					
Package T	hermal Performance	e Curve					
Air Velocity						$\Psi_{JB,\;AVG}$	
Air Velocity	y	$T_{J, MAX}$	T _T	θ _{JA/JMA}	Ψ_{JT}	$\Psi_{JB,\;AVG}$	
	y ft/min	T _{J, MAX}	(°C)	θ _{JA/JMA}	Ψ _{JT}	Ψ _{JB, AVG} (°C/W)	
m/s	-				-		
m/s	ft/min	(°C)	(°C)	(°C/W)	(°C/W)	(°C/W)	
m/s	ft/min	(°C)	(°C)	(°C/W)	(°C/W) 2.88	6.80	
Air Velocity m/s 0 0.5 1	ft/min 0 98.4	(°C) 112.7 100.7	(° C) 99.6 87.1	(°C/W) 13.74 11.11	(°C/W) 2.88 2.99	(°C/W) 6.80 6.22	

Chapter 11: Mechanical Information

Figure 42: BCM53158XU 13×13 mm² Mechanical Information



			Common Dimensions		
		Symbol	MIN.	NOM.	MAX.
Package :		LFBGA			
Body Size:	X	E	13.000		
· ·	Υ	D	13.000		<u>'</u>
Ball Pitch :		е	0.650		
Total Thickness :		А	1.167 1.252 1.3		1.337
Mold Thickness :		м	0.700 Ref.		Ref.
Substrate Thickness :		s	0.332 Ref.		Ref.
Ball Diameter :			0.300		
Stand Off :	A1	0.170		0.270	
Ball Width :		b	0.260	ı	0.360
Package Edge Tolerance :		aaa	0.050		
Mold Parallelism :		bbb	0.200		
Coplanarity:	ddd	0.080			
Ball Offset (Package) :	eee	0.150			
Ball Offset (Ball) :	fff	0.080			
Ball Count :	n	311			
Edge Ball Center to Center :	: X E1 11.700 Y D1 11.700				
- ''''	וט		11./	UU	

Chapter 12: Ordering Information

Table 64: Ordering Information

Part Number	Operational Mode	Package	Ambient Temperature
BCM53158XUB1KFBG	Unmanaged	13x13 mm ² , 311-pin FBGA	0°C to 70°C

Revision History

53158XU-DS100-R; April 11, 2018

Initial release.

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